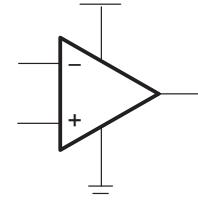


**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
OPERATIONAL AMPLIFIERS**

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- Wide Bandwidth . . . 10 MHz
- High Output Drive
  - $I_{OH}$  . . . 57 mA at  $V_{DD}$  – 1.5 V
  - $I_{OL}$  . . . 55 mA at 0.5 V
- High Slew Rate
  - SR+ . . . 16 V/ $\mu$ s
  - SR- . . . 19 V/ $\mu$ s
- Wide Supply Range . . . 4.5 V to 16 V
- Supply Current . . . 1.9 mA/Channel
- Ultralow Power Shutdown Mode
  - $I_{DD}$  . . . 125  $\mu$ A/Channel
- Low Input Noise Voltage . . . 8.5 nV/ $\sqrt{\text{Hz}}$
- Input Offset Voltage . . . 60  $\mu$ V
- Ultra-Small Packages
  - 8 or 10 Pin MSOP (TLC080/1/2/3)

Operational Amplifier



### description

The first members of TI's new BiMOS general-purpose operational amplifier family are the TLC08x. The BiMOS family concept is simple: provide an upgrade path for BiFET users who are moving away from dual-supply to single-supply systems and demand higher ac and dc performance. With performance rated from 4.5 V to 16 V across commercial (0°C to 70°C) and an extended industrial temperature range (-40°C to 125°C), BiMOS suits a wide range of audio, automotive, industrial, and instrumentation applications. Familiar features like offset nulling pins, and new features like MSOP PowerPAD™ packages and shutdown modes, enable higher levels of performance in a variety of applications.

Developed in TI's patented LBC3 BiCMOS process, the new BiMOS amplifiers combine a very high input impedance, low-noise CMOS front end with a high-drive bipolar output stage, thus providing the optimum performance features of both. AC performance improvements over the TL08x BiFET predecessors include a bandwidth of 10 MHz (an increase of 300%) and voltage noise of 8.5 nV/ $\sqrt{\text{Hz}}$  (an improvement of 60%). DC improvements include an ensured  $V_{ICR}$  that includes ground, a factor of 4 reduction in input offset voltage down to 1.5 mV (maximum) in the standard grade, and a power supply rejection improvement of greater than 40 dB to 130 dB. Added to this list of impressive features is the ability to drive  $\pm 50$ -mA loads comfortably from an ultrasmall-footprint MSOP PowerPAD package, which positions the TLC08x as the ideal high-performance general-purpose operational amplifier family.

FAMILY PACKAGE TABLE

DEVICE	NO. OF CHANNELS	PACKAGE TYPES				SHUTDOWN	UNIVERSAL EVM BOARD
		MSOP	PDIP	SOIC	TSSOP		
TLC080	1	8	8	8	—	Yes	Refer to the EVM Selection Guide (Lit# SLOU060)
TLC081	1	8	8	8	—	—	
TLC082	2	8	8	8	—	—	
TLC083	2	10	14	14	—	Yes	
TLC084	4	—	14	14	20	—	
TLC085	4	—	16	16	20	Yes	



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
OPERATIONAL AMPLIFIERS**

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**TLC080 and TLC081 AVAILABLE OPTIONS**

TA	PACKAGED DEVICES			
	SMALL OUTLINE (D) <sup>†</sup>	SMALL OUTLINE (DGN) <sup>†</sup>	SYMBOL	PLASTIC DIP (P)
0°C to 70°C	TLC080CD TLC081CD	TLC080CDGN TLC081CDGN	xxTIACW xxTIACY	TLC080CP TLC081CP
-40°C to 125°C	TLC080ID TLC081ID	TLC080IDGN TLC081IDGN	xxTIACX xxTIACZ	TLC080IP TLC081IP
	TLC080AID TLC081AID	—	—	TLC080AIP TLC081AIP

<sup>†</sup> This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLC080CDR).

**TLC082 and TLC083 AVAILABLE OPTIONS**

TA	PACKAGED DEVICES					PLASTIC DIP (N)	PLASTIC DIP (P)		
	SMALL OUTLINE (D) <sup>†</sup>	MSOP							
		(DGN) <sup>†</sup>	SYMBOL <sup>‡</sup>	(DGQ) <sup>†</sup>	SYMBOL <sup>‡</sup>				
0°C to 70°C	TLC082CD TLC083CD	TLC082CDGN —	xxTIADZ —	— TLC083CDGQ	— xxTIAEB	— TLC083CN	TLC082CP —		
-40°C to 125°C	TLC082ID TLC083ID	TLC082IDGN —	xxTIAEA —	— TLC083IDGQ	— xxTIAEC	— TLC083IN	TLC082IP —		
	TLC082AID TLC083AID	— —	— —	— —	— —	— TLC083AIN	TLC082AIP —		

<sup>†</sup> This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLC082CDR).

<sup>‡</sup> xx represents the device date code.

**TLC084 and TLC085 AVAILABLE OPTIONS**

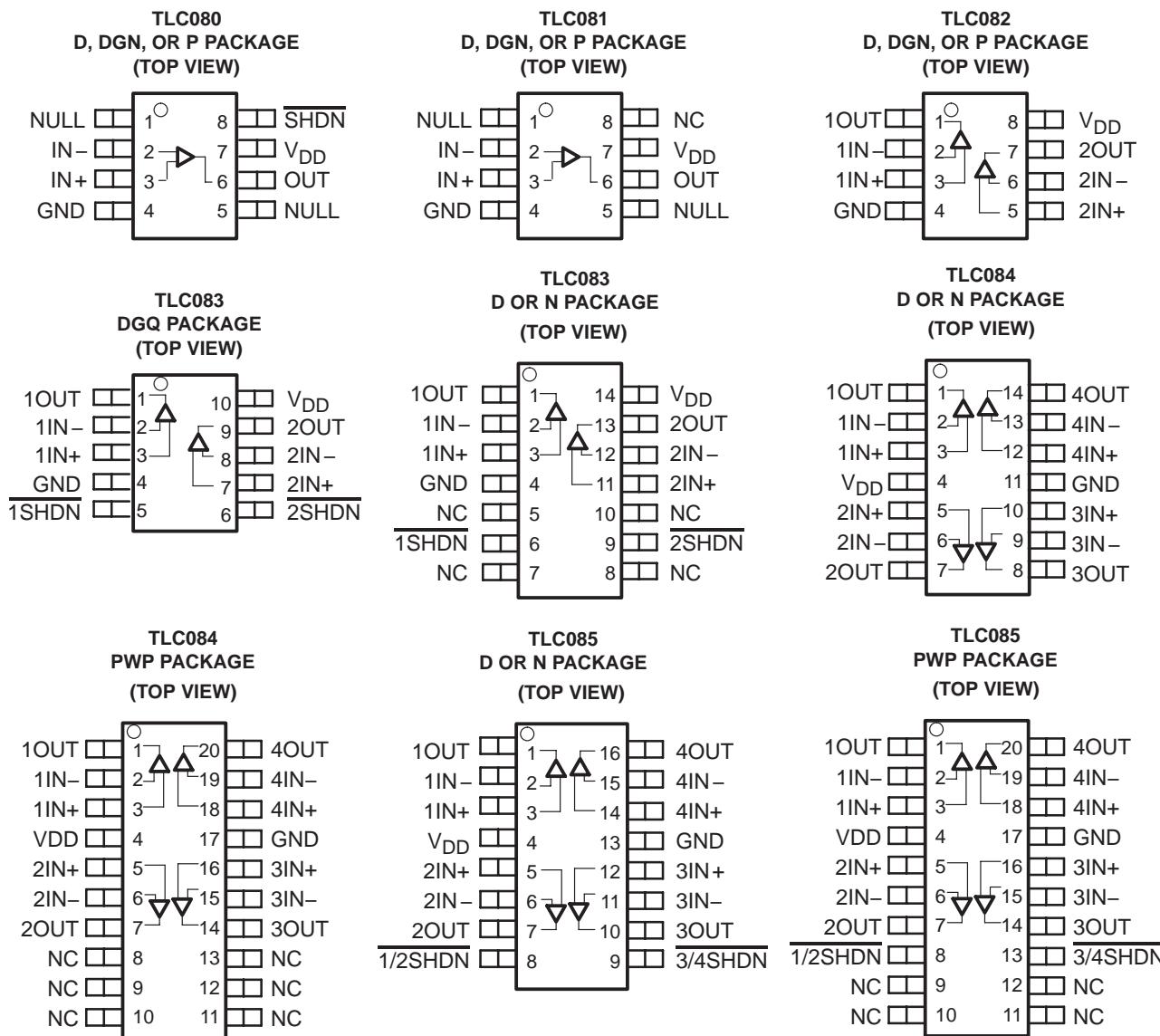
TA	PACKAGED DEVICES		
	SMALL OUTLINE (D) <sup>†</sup>	PLASTIC DIP (N)	TSSOP (PWP) <sup>†</sup>
0°C to 70°C	TLC084CD TLC085CD	TLC084CN TLC085CN	TLC084CPWP TLC085CPWP
-40°C to 125°C	TLC084ID TLC085ID	TLC084IN TLC085IN	TLC084IPWP TLC085IPWP
	TLC084AID TLC085AID	TLC084AIN TLC085AIN	TLC084AIPWP TLC085AIPWP

<sup>†</sup> This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLC084CDR).

For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or see the TI web site at [www.ti.com](http://www.ti.com).

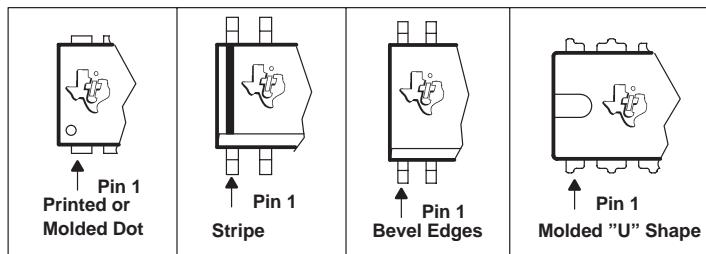
**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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**TLC08x PACKAGE PINOUTS**



NC – No internal connection

**TYPICAL PIN 1 INDICATORS**



**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>**

Supply voltage, $V_{DD}$ (see Note 1) .....	17 V
Differential input voltage range, $V_{ID}$ .....	$\pm V_{DD}$
Continuous total power dissipation .....	See Dissipation Rating Table
Operating free-air temperature range, $T_A$ : C suffix .....	0°C to 70°C
I suffix .....	-40°C to 125°C
Maximum junction temperature, $T_J$ .....	150°C
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .....	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to GND.

**DISSIPATION RATING TABLE**

PACKAGE	$\theta_{JC}$ (°C/W)	$\theta_{JA}$ (°C/W)	$T_A \leq 25^\circ\text{C}$ POWER RATING
D (8)	38.3	176	710 mW
D (14)	26.9	122.3	1022 mW
D (16)	25.7	114.7	1090 mW
DGN (8)	4.7	52.7	2.37 W
DGQ (10)	4.7	52.3	2.39 W
N (14, 16)	32	78	1600 mW
P (8)	41	104	1200 mW
PWP (20)	1.40	26.1	4.79 W

**recommended operating conditions**

		MIN	MAX	UNIT
Supply voltage, $V_{DD}$	Single supply	4.5	16	V
	Split supply	$\pm 2.25$	$\pm 8$	
Common-mode input voltage, $V_{ICR}$		GND	$V_{DD}-2$	V
Shutdown on/off voltage level <sup>‡</sup>	$V_{IH}$	2		V
	$V_{IL}$		0.8	
Operating free-air temperature, $T_A$	C-suffix	0	70	°C
	I-suffix	-40	125	

<sup>‡</sup> Relative to the voltage on the GND terminal of the device.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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electrical characteristics at specified free-air temperature,  $V_{DD} = 5$  V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
$V_{IO}$	Input offset voltage	$V_{DD} = 5$ V, $V_{IC} = 2.5$ V, $V_O = 2.5$ V, $R_S = 50 \Omega$	$TLC080/1/2/3$ , $TLC084/5$	25°C	390	1900	$\mu$ V
			Full range			3000	
			$TLC080/1/2/3A$ , $TLC084/5A$	25°C	390	1400	
			Full range			2000	
$\alpha V_{IO}$	Temperature coefficient of input offset voltage				1.2		$\mu$ V/°C
$I_{IO}$	Input offset current	$V_{DD} = 5$ V, $V_{IC} = 2.5$ V, $V_O = 2.5$ V, $R_S = 50 \Omega$	$TLC08XC$	25°C	1.9	50	$p$ A
			$TLC08XI$	Full range		100	
						700	
				25°C	3	50	
$I_{IB}$	Input bias current	$TLC08XC$ $TLC08XI$		Full range	100		$p$ A
						700	
				25°C	0	0	
				Full range	0	0	
$V_{ICR}$	Common-mode input voltage	$R_S = 50 \Omega$		25°C	to 3.0	to 3.5	V
				Full range	0	0	
					to 3.0	to 3.5	
				25°C	0	0	
$V_{OH}$	High-level output voltage	$V_{IC} = 2.5$ V	$I_{OH} = -1$ mA	25°C	4.1	4.3	V
				Full range	3.9		
			$I_{OH} = -20$ mA	25°C	3.7	4	
				Full range	3.5		
			$I_{OH} = -35$ mA	25°C	3.4	3.8	
				Full range	3.2		
			$I_{OH} = -50$ mA	25°C	3.2	3.6	
				-40°C to 85°C	3		
$V_{OL}$	Low-level output voltage	$V_{IC} = 2.5$ V	$I_{OL} = 1$ mA	25°C	0.18	0.25	V
				Full range		0.35	
			$I_{OL} = 20$ mA	25°C	0.35	0.39	
				Full range		0.45	
			$I_{OL} = 35$ mA	25°C	0.43	0.55	
				Full range		0.7	
			$I_{OL} = 50$ mA	25°C	0.45	0.63	
				-40°C to 85°C		0.7	
$I_{OS}$	Short-circuit output current		Sourcing	25°C	100		mA
			Sinking	25°C	100		
$I_O$	Output current	$V_{OH} = 1.5$ V from positive rail $V_{OL} = 0.5$ V from negative rail	$V_{OH} = 1.5$ V from positive rail	25°C	57		mA
			$V_{OL} = 0.5$ V from negative rail	25°C	55		

<sup>†</sup> Full range is 0°C to 70°C for C suffix and -40°C to 125°C for I suffix. If not specified, full range is -40°C to 125°C.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
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**electrical characteristics at specified free-air temperature,  $V_{DD} = 5$  V (unless otherwise noted)  
(continued)**

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
A <sub>VD</sub> Large-signal differential voltage amplification	$V_{O(PP)} = 3$ V, $R_L = 10$ k $\Omega$	25°C	100	120		dB
		Full range	100			
r <sub>i(d)</sub> Differential input resistance		25°C	1000			GeV
C <sub>iC</sub> Common-mode input capacitance	f = 10 kHz	25°C	22.9			pF
z <sub>o</sub> Closed-loop output impedance	f = 10 kHz, $A_V = 10$	25°C	0.25			$\Omega$
CMRR Common-mode rejection ratio	$V_{IC} = 0$ to 3 V, $R_S = 50$ $\Omega$	25°C	80	110		dB
		Full range	80			
k <sub>SVR</sub> Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 4.5$ V to 16 V, $V_{IC} = V_{DD}/2$ , No load	25°C	80	100		dB
		Full range	80			
I <sub>DD</sub> Supply current (per channel)	$V_O = 2.5$ V, No load	25°C	1.8	2.5		mA
		Full range	3.5			
I <sub>DD(SHDN)</sub> Supply current in shutdown mode (per channel) (TLC080, TLC083, TLC085)	$SHDN \leq 0.8$ V	25°C	125	200		$\mu$ A
		Full range	250			

† Full range is 0°C to 70°C for C suffix and –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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operating characteristics at specified free-air temperature,  $V_{DD} = 5$  V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		TA <sup>†</sup>	MIN	TYP	MAX	UNIT	
SR+	Positive slew rate at unity gain	$V_O(PP) = 0.8$ V, $C_L = 50$ pF, $R_L = 10$ k $\Omega$		25°C	10	16		V/ $\mu$ s	
				Full range	9.5				
SR-	Negative slew rate at unity gain	$V_O(PP) = 0.8$ V, $C_L = 50$ pF, $R_L = 10$ k $\Omega$		25°C	12.5	19		V/ $\mu$ s	
				Full range	10				
V <sub>n</sub>	Equivalent input noise voltage	$f = 100$ Hz		25°C	12			nV/ $\sqrt$ Hz	
		$f = 1$ kHz		25°C	8.5				
I <sub>n</sub>	Equivalent input noise current	$f = 1$ kHz		25°C	0.6			fA/ $\sqrt$ Hz	
THD + N	Total harmonic distortion plus noise	$V_O(PP) = 3$ V, $R_L = 10$ k $\Omega$ and 250 $\Omega$ , $f = 1$ kHz		25°C	0.002%				
					0.012%				
					0.085%				
t(on)	Amplifier turnon time <sup>‡</sup>	$R_L = 10$ k $\Omega$		25°C	0.15			$\mu$ s	
t(off)	Amplifier turnoff time <sup>‡</sup>			25°C	1.3			$\mu$ s	
Gain-bandwidth product		$f = 10$ kHz, $R_L = 10$ k $\Omega$		25°C	10			MHz	
t <sub>s</sub>	Settling time	$V_{(STEP)PP} = 1$ V, $A_V = -1$ , $C_L = 10$ pF, $R_L = 10$ k $\Omega$		25°C	0.18			$\mu$ s	
					0.39				
		$V_{(STEP)PP} = 1$ V, $A_V = -1$ , $C_L = 47$ pF, $R_L = 10$ k $\Omega$		25°C	0.18				
					0.39				
φ <sub>m</sub>	Phase margin	$R_L = 10$ k $\Omega$ , $C_L = 50$ pF		25°C	32°				
		$R_L = 10$ k $\Omega$ , $C_L = 0$ pF			40°				
	Gain margin	$R_L = 10$ k $\Omega$ , $C_L = 50$ pF		25°C	2.2			dB	
		$R_L = 10$ k $\Omega$ , $C_L = 0$ pF			3.3				

<sup>†</sup> Full range is 0°C to 70°C for C suffix and –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

<sup>‡</sup> Disable time and enable time are defined as the interval between application of the logic signal to SHDN and the point at which the supply current has reached half its final value.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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**electrical characteristics at specified free-air temperature,  $V_{DD} = 12$  V (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT	
$V_{IO}$ Input offset voltage	$V_{DD} = 12$ V $V_{IC} = 6$ V, $V_O = 6$ V, $R_S = 50 \Omega$	TLC0841/2/3, TLC084/5	25°C	390	1900	$\mu$ V	
		Full range			3000		
		TLC0841/2/3A, TLC084/5A	25°C	390	1400		
		Full range			2000		
$\alpha V_{IO}$ Temperature coefficient of input offset voltage				1.2		$\mu$ V/°C	
$I_{IO}$ Input offset current	$V_{DD} = 12$ V $V_{IC} = 6$ V, $V_O = 6$ V, $R_S = 50 \Omega$	TLC08xC	25°C	1.5	50	$p$ A	
		Full range			100		
$I_{IB}$ Input bias current	$V_{DD} = 12$ V $V_{IC} = 6$ V, $V_O = 6$ V, $R_S = 50 \Omega$	TLC08xC	25°C	2	50	$p$ A	
		Full range			100		
		TLC08xl			700		
$V_{ICR}$ Common-mode input voltage	$R_S = 50 \Omega$		25°C	0	0	V	
				to	to		
				10.0	10.5		
		Full range		0	0		
				to	to		
				10.0	10.5		
$V_{OH}$ High-level output voltage	$V_{IC} = 6$ V	$I_{OH} = -1$ mA	25°C	11.1	11.2	V	
			Full range	11			
		$I_{OH} = -20$ mA	25°C	10.8	11		
			Full range	10.7			
		$I_{OH} = -35$ mA	25°C	10.6	10.7		
			Full range	10.3			
		$I_{OH} = -50$ mA	25°C	10.3	10.5		
			-40°C to 85°C	10.2			
$V_{OL}$ Low-level output voltage	$V_{IC} = 6$ V	$I_{OL} = 1$ mA	25°C	0.17	0.25	V	
			Full range		0.35		
		$I_{OL} = 20$ mA	25°C	0.35	0.45		
			Full range		0.5		
		$I_{OL} = 35$ mA	25°C	0.4	0.52		
			Full range		0.6		
		$I_{OL} = 50$ mA	25°C	0.45	0.6		
			-40°C to 85°C		0.65		
$I_{OS}$ Short-circuit output current	Sourcing		25°C	150		$mA$	
	Sinking		25°C	150			
$I_O$ Output current	$V_{OH} = 1.5$ V from positive rail		25°C	57		$mA$	
	$V_{OL} = 0.5$ V from negative rail		25°C	55			

† Full range is 0°C to 70°C for C suffix and -40°C to 125°C for I suffix. If not specified, full range is -40°C to 125°C.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY  
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**electrical characteristics at specified free-air temperature,  $V_{DD} = 12$  V (unless otherwise noted)  
(continued)**

PARAMETER	TEST CONDITIONS	$T_A$ †	MIN	TYP	MAX	UNIT
A <sub>VD</sub> Large-signal differential voltage amplification	$V_{O(PP)} = 8$ V, $R_L = 10$ k $\Omega$	25°C	120	140		dB
		Full range	120			
$r_{i(d)}$ Differential input resistance		25°C	1000			G $\Omega$
C <sub>IC</sub> Common-mode input capacitance	f = 10 kHz	25°C	21.6			pF
$z_0$ Closed-loop output impedance	f = 10 kHz, $A_V = 10$	25°C	0.25			$\Omega$
CMRR Common-mode rejection ratio	$V_{IC} = 0$ to 10 V, $R_S = 50$ $\Omega$	25°C	80	110		dB
		Full range	80			
k <sub>SVR</sub> Supply voltage rejection ratio ( $\Delta V_{DD} / \Delta V_{IO}$ )	$V_{DD} = 4.5$ V to 16 V, $V_{IC} = V_{DD}/2$ , No load	25°C	80	100		dB
		Full range	80			
I <sub>DD</sub> Supply current (per channel)	$V_O = 7.5$ V, No load	25°C	1.9	2.9		mA
		Full range		3.5		
I <sub>DD(SHDN)</sub> Supply current in shutdown mode (TLC080, TLC083, TLC085) (per channel)	$SHDN \leq 0.8$ V	25°C	125	200		$\mu$ A
		Full range		250		

† Full range is 0°C to 70°C for C suffix and –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

**TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA  
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**operating characteristics at specified free-air temperature,  $V_{DD} = 12$  V (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		TA <sup>†</sup>	MIN	TYP	MAX	UNIT	
SR+	Positive slew rate at unity gain	$V_{O(PP)} = 2$ V, $R_L = 10$ k $\Omega$	$C_L = 50$ pF,	25°C	10	16		V/ $\mu$ s	
				Full range	9.5				
SR-	Negative slew rate at unity gain	$V_{O(PP)} = 2$ V, $R_L = 10$ k $\Omega$	$C_L = 50$ pF,	25°C	12.5	19		V/ $\mu$ s	
				Full range	10				
V <sub>n</sub>	Equivalent input noise voltage	$f = 100$ Hz		25°C		14		nV/ $\sqrt{\text{Hz}}$	
				25°C		8.5			
I <sub>n</sub>	Equivalent input noise current	$f = 1$ kHz		25°C		0.6		fA/ $\sqrt{\text{Hz}}$	
THD + N	Total harmonic distortion plus noise	$V_{O(PP)} = 8$ V, $R_L = 10$ k $\Omega$ and 250 $\Omega$ , $f = 1$ kHz	$A_V = 1$ $A_V = 10$ $A_V = 100$	25°C		0.002%			
						0.005%			
						0.022%			
t(on)	Amplifier turnon time <sup>‡</sup>	$R_L = 10$ k $\Omega$		25°C		0.47		$\mu$ s	
t(off)	Amplifier turnoff time <sup>‡</sup>			25°C		2.5		$\mu$ s	
Gain-bandwidth product		$f = 10$ kHz, $R_L = 10$ k $\Omega$		25°C		10		MHz	
t <sub>s</sub>	Settling time	$V_{(STEP)PP} = 1$ V, $A_V = -1$ , $C_L = 10$ pF, $R_L = 10$ k $\Omega$	0.1% 0.01%	25°C		0.17		$\mu$ s	
						0.22			
		$V_{(STEP)PP} = 1$ V, $A_V = -1$ , $C_L = 47$ pF, $R_L = 10$ k $\Omega$	0.1% 0.01%			0.17			
						0.29			
$\phi_m$	Phase margin	$R_L = 10$ k $\Omega$ , $C_L = 50$ pF		25°C		37°			
		$R_L = 10$ k $\Omega$ , $C_L = 0$ pF				42°			
	Gain margin	$R_L = 10$ k $\Omega$ , $C_L = 50$ pF		25°C		3.1		dB	
		$R_L = 10$ k $\Omega$ , $C_L = 0$ pF				4			

<sup>†</sup> Full range is 0°C to 70°C for C suffix and –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

<sup>‡</sup> Disable time and enable time are defined as the interval between application of the logic signal to SHDN and the point at which the supply current has reached half its final value.

## TYPICAL CHARACTERISTICS

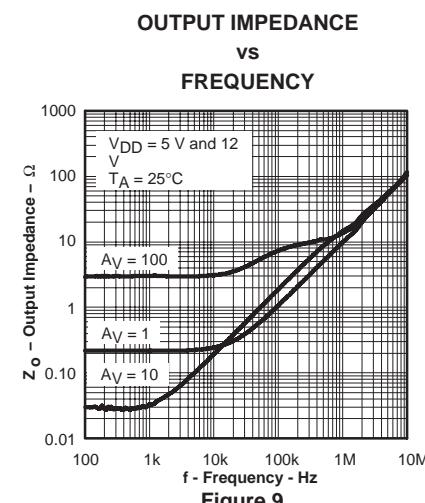
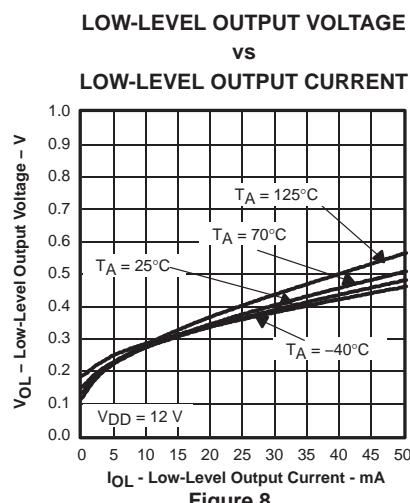
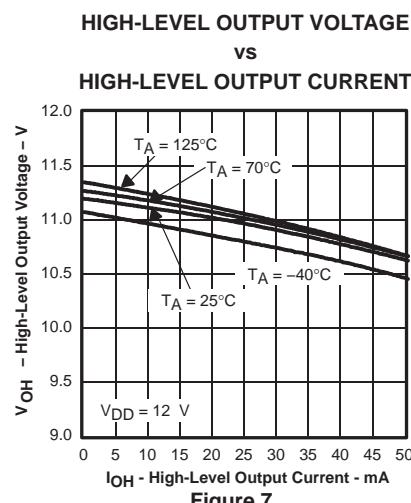
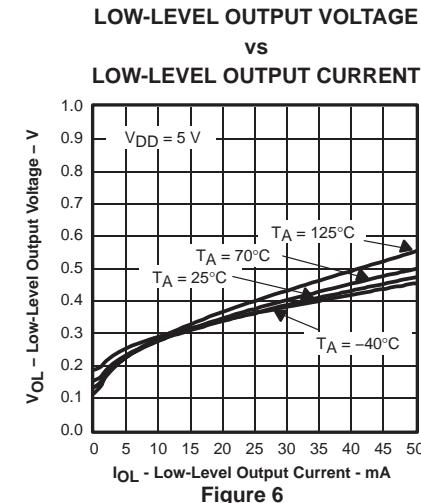
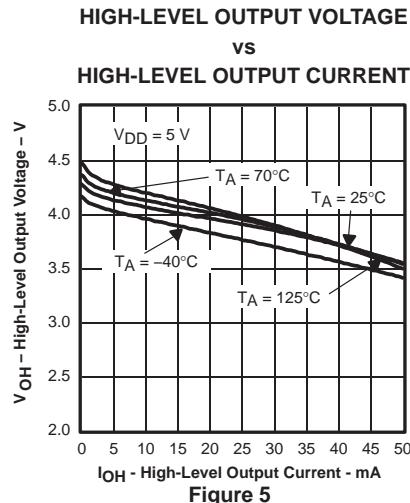
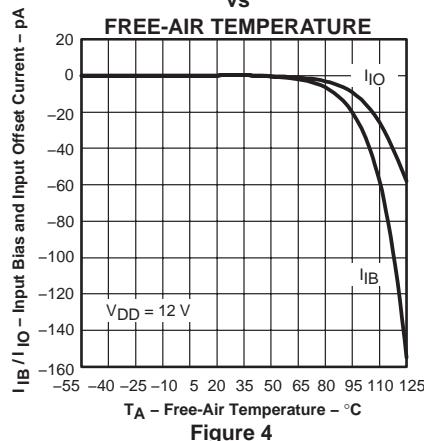
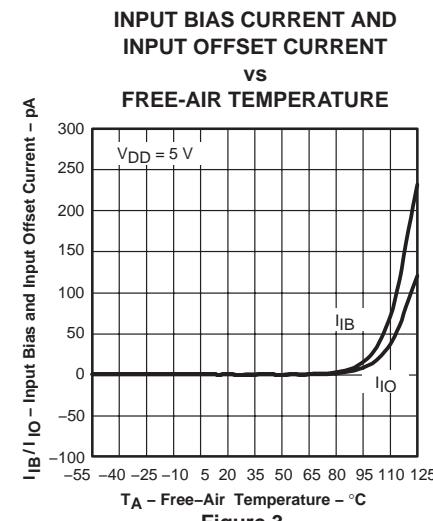
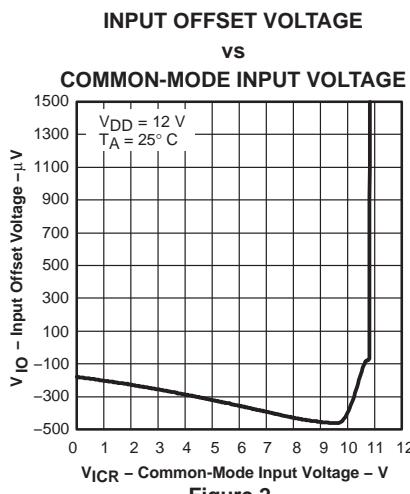
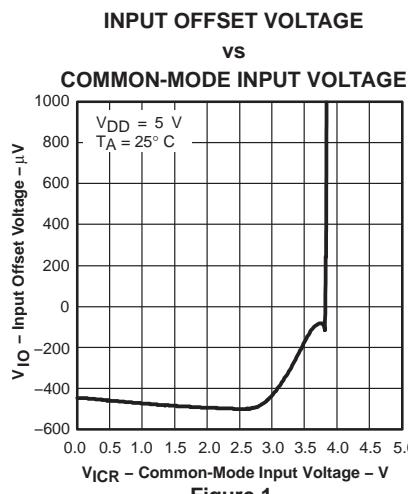
**Table of Graphs**

			<b>FIGURE</b>
$V_{IO}$	Input offset voltage	vs Common-mode input voltage	1, 2
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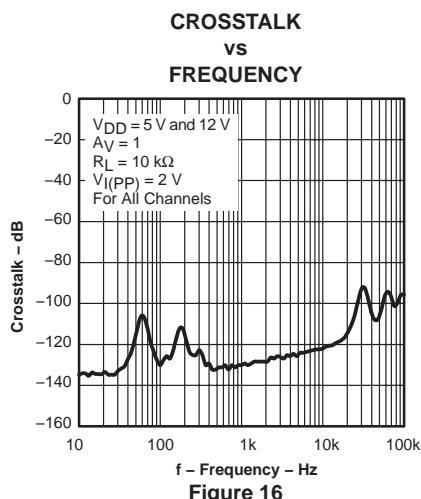
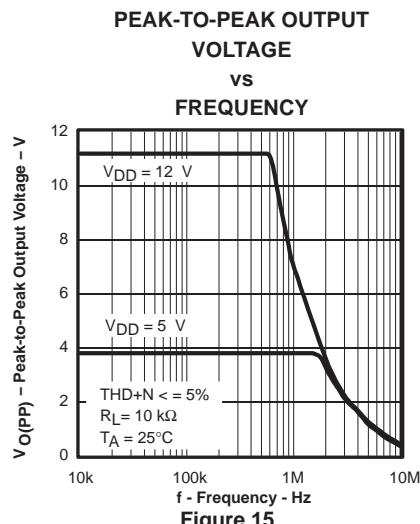
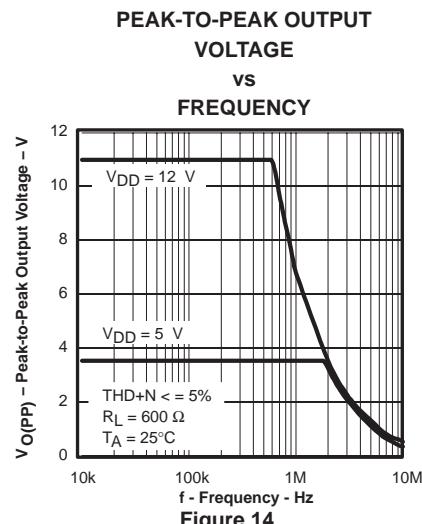
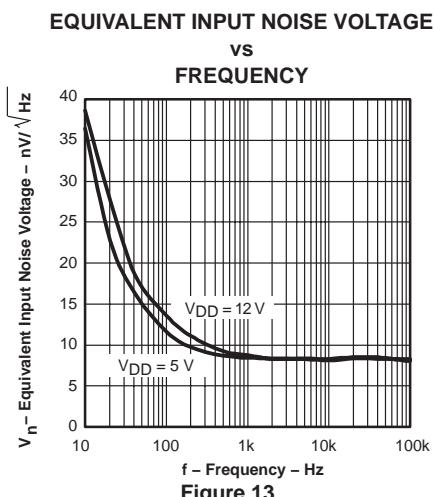
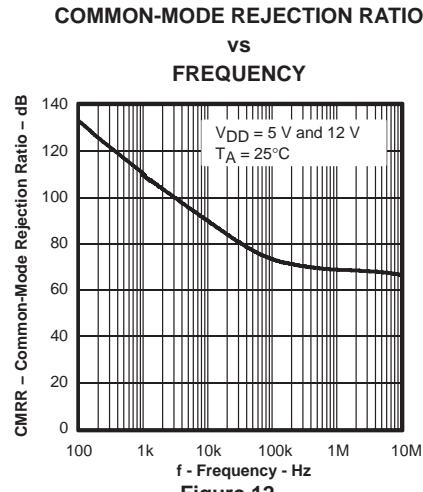
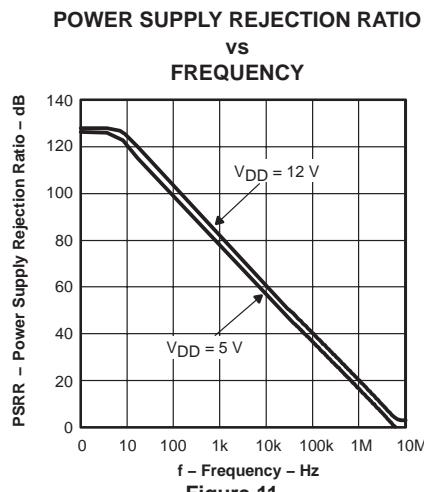
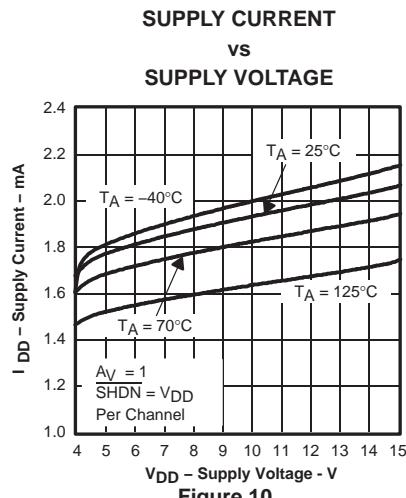
# TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY OPERATIONAL AMPLIFIERS

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## TYPICAL CHARACTERISTICS



## TYPICAL CHARACTERISTICS

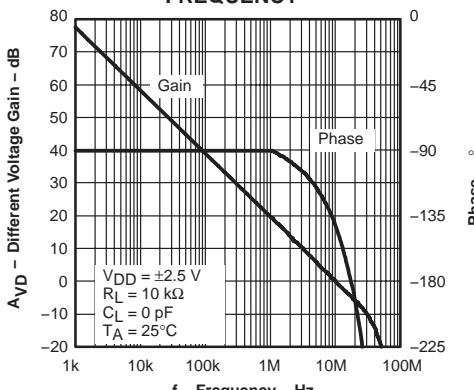


# TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY OPERATIONAL AMPLIFIERS

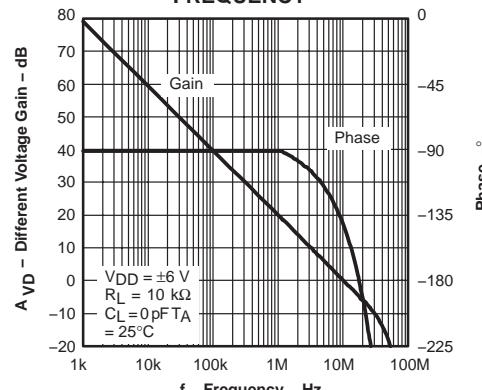
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## TYPICAL CHARACTERISTICS

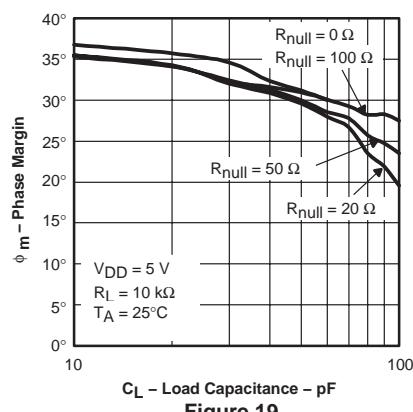
### DIFFERENTIAL VOLTAGE GAIN AND PHASE vs FREQUENCY



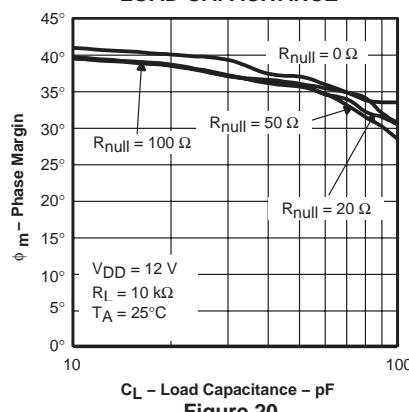
### DIFFERENTIAL VOLTAGE GAIN AND PHASE vs FREQUENCY



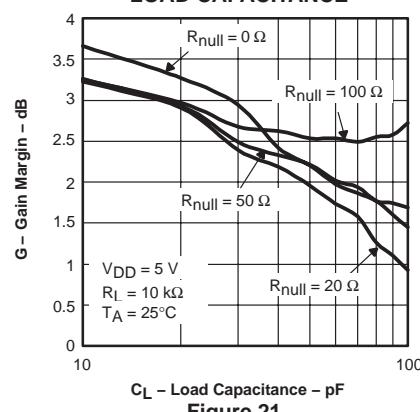
### PHASE MARGIN vs LOAD CAPACITANCE



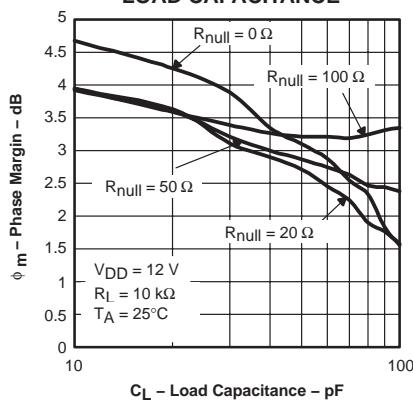
### PHASE MARGIN vs LOAD CAPACITANCE



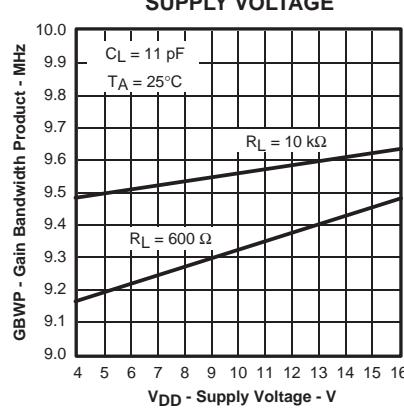
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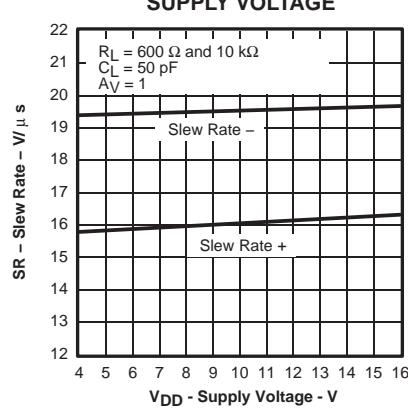
### GAIN MARGIN vs LOAD CAPACITANCE



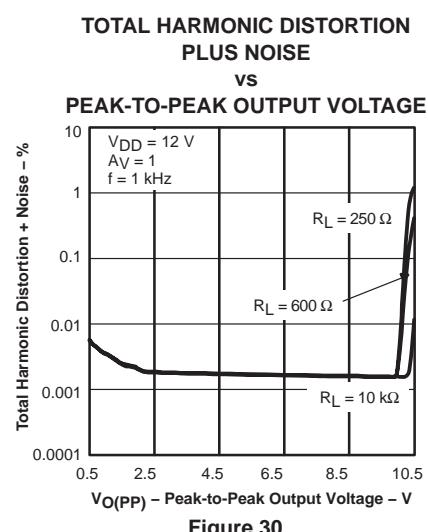
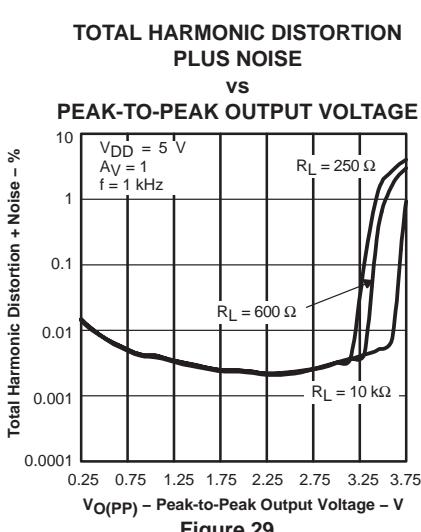
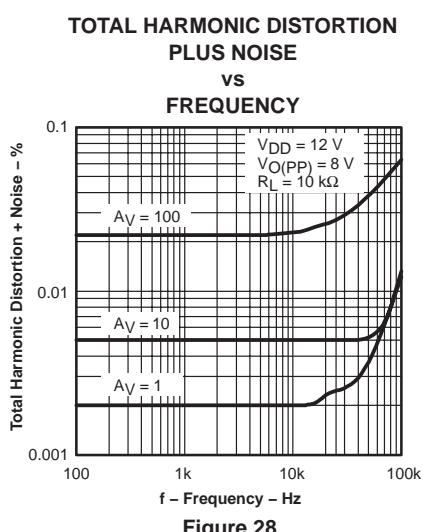
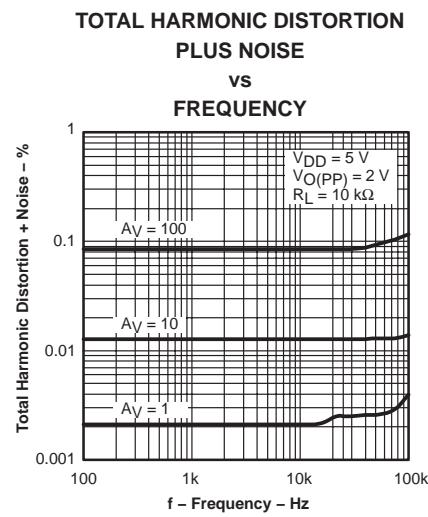
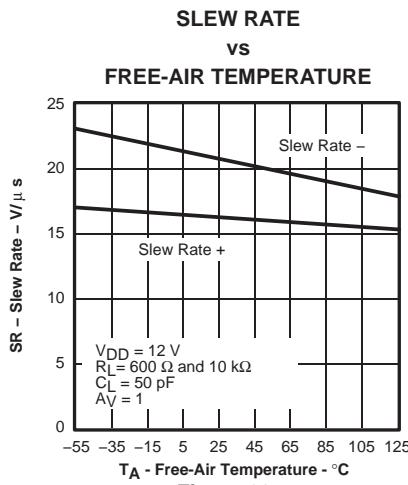
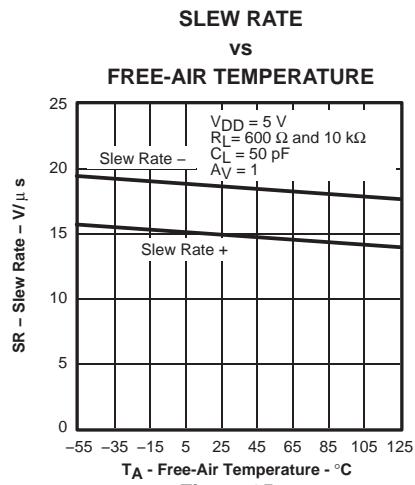
### GAIN BANDWIDTH PRODUCT vs SUPPLY VOLTAGE



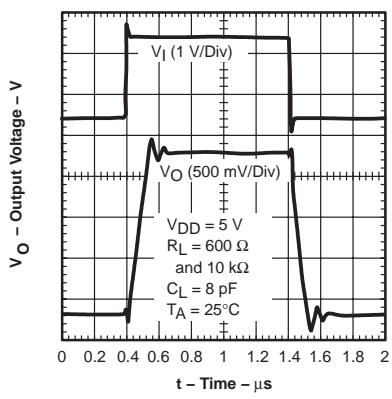
### SLEW RATE vs SUPPLY VOLTAGE



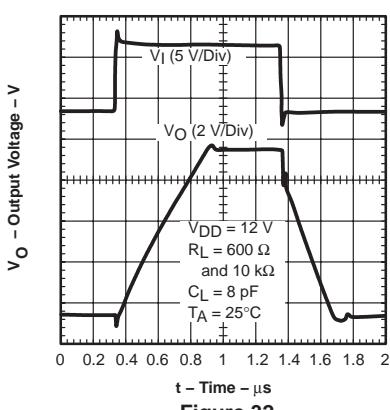
**TYPICAL CHARACTERISTICS**



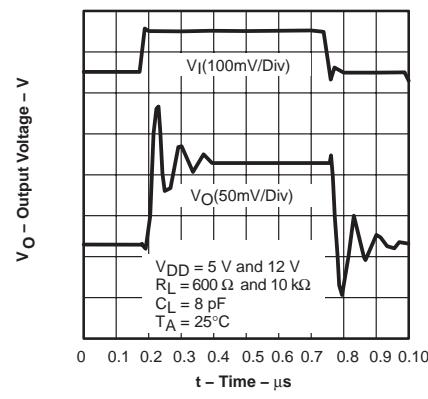
**LARGE SIGNAL FOLLOWER  
PULSE RESPONSE**



**LARGE SIGNAL FOLLOWER  
PULSE RESPONSE**



**SMALL SIGNAL FOLLOWER PULSE  
RESPONSE**



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## TYPICAL CHARACTERISTICS

### LARGE SIGNAL INVERTING PULSE RESPONSE

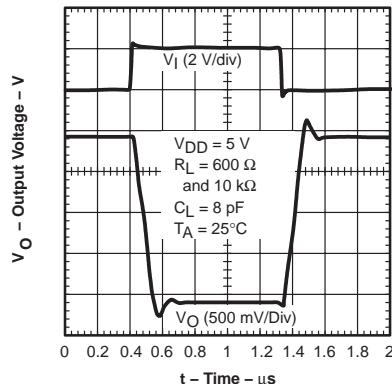


Figure 34

### LARGE SIGNAL INVERTING PULSE RESPONSE

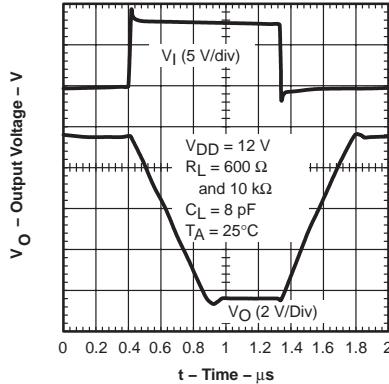


Figure 35

### SMALL SIGNAL INVERTING PULSE RESPONSE

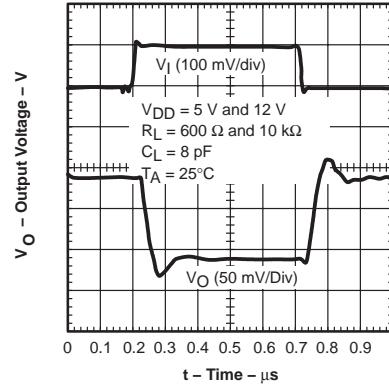


Figure 36

### SHUTDOWN FORWARD ISOLATION VS FREQUENCY

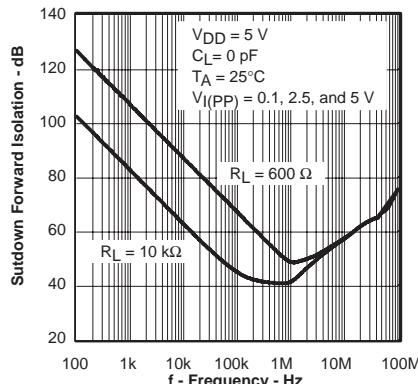


Figure 37

### SHUTDOWN FORWARD ISOLATION VS FREQUENCY

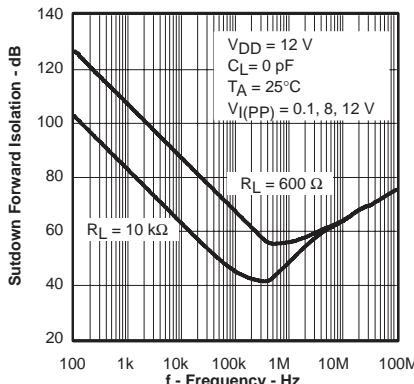


Figure 38

### SHUTDOWN REVERSE ISOLATION VS FREQUENCY

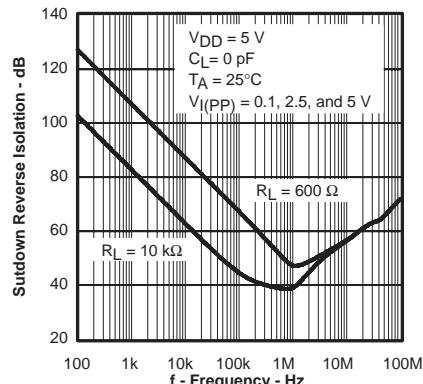


Figure 39

### SHUTDOWN REVERSE ISOLATION VS FREQUENCY

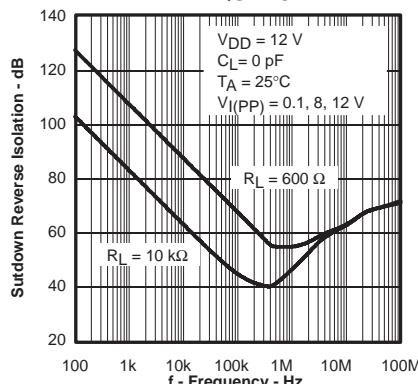


Figure 40

### SHUTDOWN SUPPLY CURRENT VS SUPPLY VOLTAGE

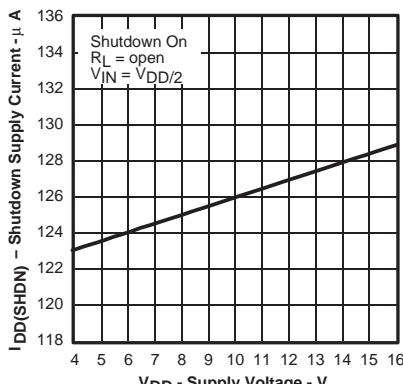


Figure 41

### SHUTDOWN SUPPLY CURRENT VS FREE-AIR TEMPERATURE

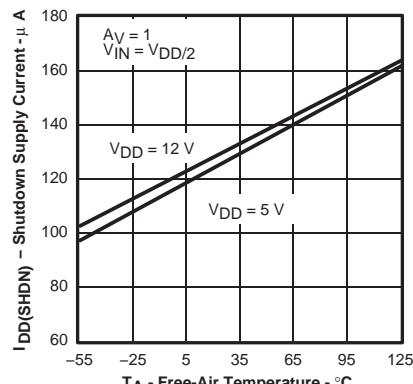
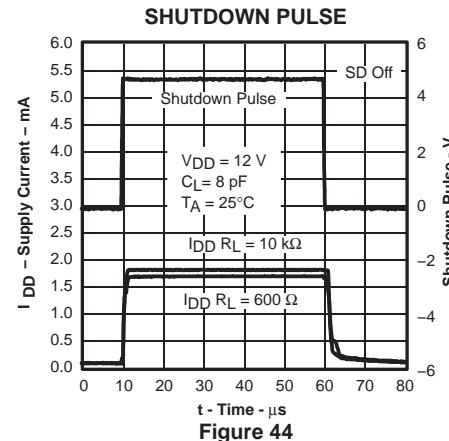
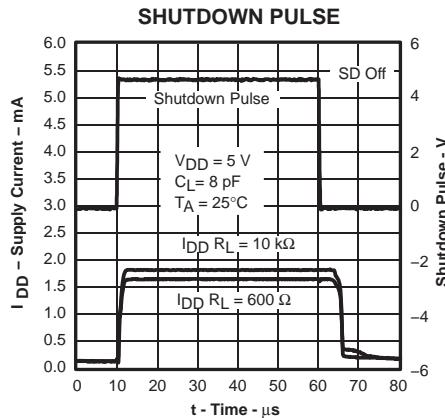
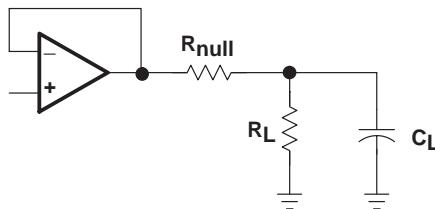


Figure 42

**TYPICAL CHARACTERISTICS**



**PARAMETER MEASUREMENT INFORMATION**

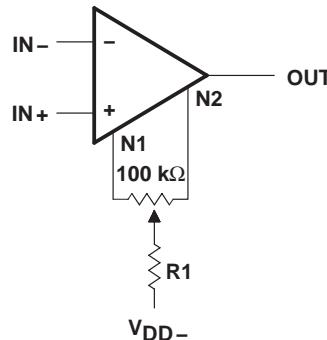


**Figure 45**

**APPLICATION INFORMATION**

**input offset voltage null circuit**

The TLC080 and TLC081 has an input offset nulling function. Refer to Figure 46 for the diagram.



NOTE A:  $R_1 = 5.6 \text{ k}\Omega$  for offset voltage adjustment of  $\pm 10 \text{ mV}$ .  
 $R_1 = 20 \text{ k}\Omega$  for offset voltage adjustment of  $\pm 3 \text{ mV}$ .

**Figure 46. Input Offset Voltage Null Circuit**

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## APPLICATION INFORMATION

### driving a capacitive load

When the amplifier is configured in this manner, capacitive loading directly on the output will decrease the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series ( $R_{NULL}$ ) with the output of the amplifier, as shown in Figure 47. A minimum value of 20  $\Omega$  should work well for most applications.

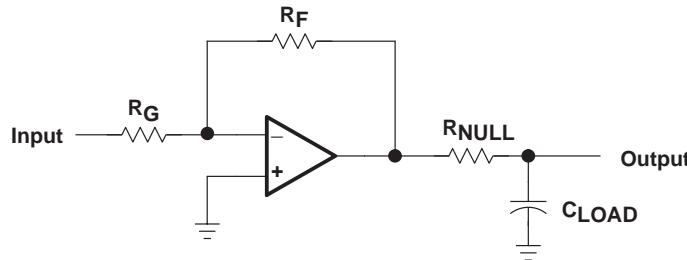


Figure 47. Driving a Capacitive Load

### offset voltage

The output offset voltage, ( $V_{OO}$ ) is the sum of the input offset voltage ( $V_{IO}$ ) and both input bias currents ( $I_{IB}$ ) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

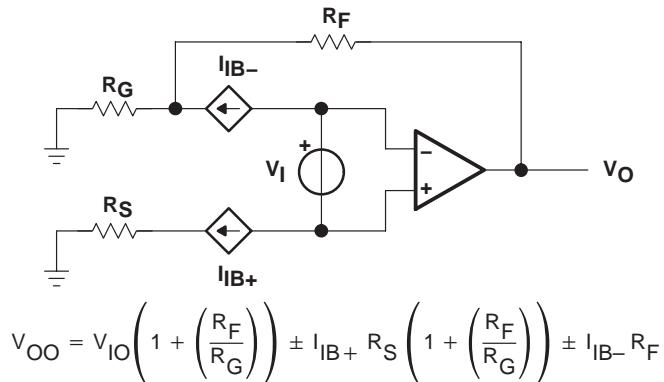


Figure 48. Output Offset Voltage Model

## APPLICATION INFORMATION

### high speed CMOS input amplifiers

The TLC08x is a family of high-speed low-noise CMOS input operational amplifiers that has an input capacitance of the order of 20 pF. Any resistor used in the feedback path adds a pole in the transfer function equivalent to the input capacitance multiplied by the combination of source resistance and feedback resistance. For example, a gain of  $-10$ , a source resistance of  $1\text{ k}\Omega$ , and a feedback resistance of  $10\text{ k}\Omega$  add an additional pole at approximately 8 MHz. This is more apparent with CMOS amplifiers than bipolar amplifiers due to their greater input capacitance.

This is of little consequence on slower CMOS amplifiers, as this pole normally occurs at frequencies above their unity-gain bandwidth. However, the TLC08x with its 10-MHz bandwidth means that this pole normally occurs at frequencies where there is only on the order of 5dB gain left and the phase shift adds considerably.

The effect of this pole is the strongest with large feedback resistances at small closed loop gains. As the feedback resistance is increased, the gain peaking increases at a lower frequency and the  $180^\circ$  phase shift crossover point also moves down in frequency, decreasing the phase margin.

For the TLC08x, the maximum feedback resistor recommended is  $5\text{ k}\Omega$ ; larger resistances can be used but a capacitor in parallel with the feedback resistor is recommended to counter the effects of the input capacitance pole.

The TLC083 with a 1-V step response has an 80% overshoot with a natural frequency of 3.5 MHz when configured as a unity gain buffer and with a  $10\text{ k}\Omega$  feedback resistor. By adding a 10-pF capacitor in parallel with the feedback resistor, the overshoot is reduced to 40% and eliminates the natural frequency, resulting in a much faster settling time (see Figure 49). The 10-pF capacitor was chosen for convenience only.

Load capacitance had little effect on these measurements due to the excellent output drive capability of the TLC08x.

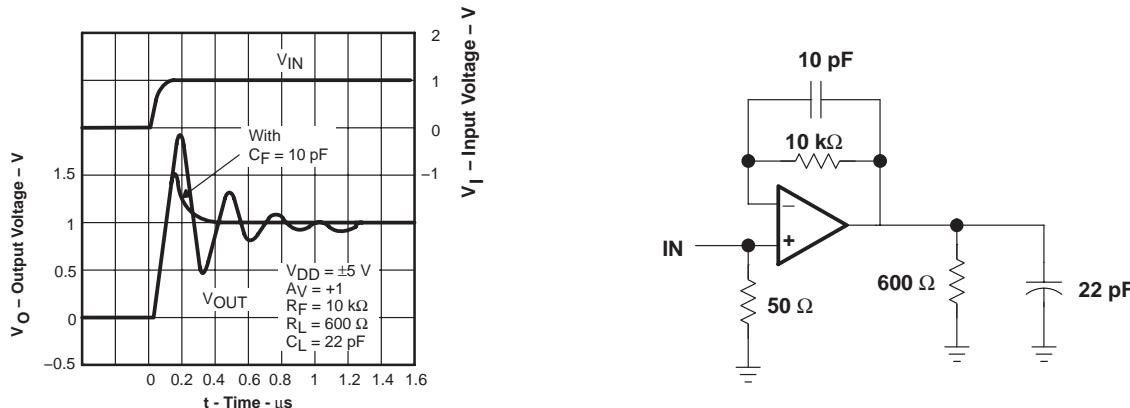


Figure 49. 1-V Step Response

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## APPLICATION INFORMATION

### general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 50).

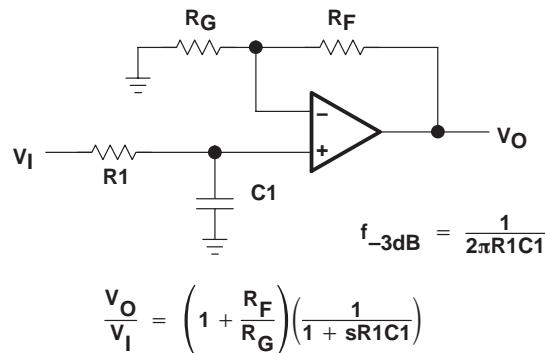


Figure 50. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

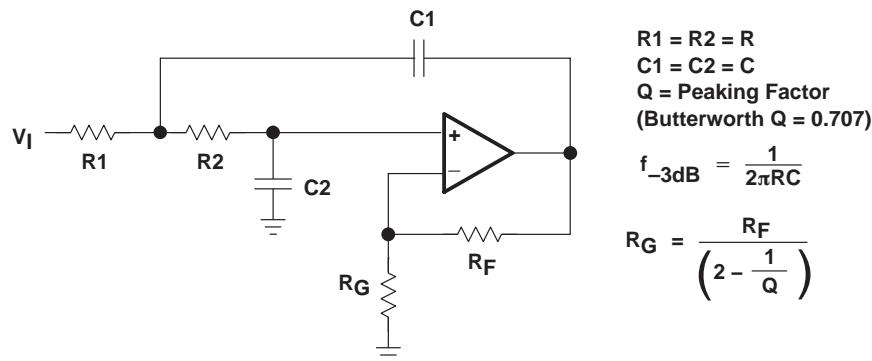


Figure 51. 2-Pole Low-Pass Sallen-Key Filter

## APPLICATION INFORMATION

### shutdown function

Three members of the TLC08x family (TLC080/3/5) have a shutdown terminal ( $\overline{SHDN}$ ) for conserving battery life in portable applications. When the shutdown terminal is tied low, the supply current is reduced to 125  $\mu$ A/channel, the amplifier is disabled, and the outputs are placed in a high-impedance mode. To enable the amplifier, the shutdown terminal can either be left floating or pulled high. When the shutdown terminal is left floating, care should be taken to ensure that parasitic leakage current at the shutdown terminal does not inadvertently place the operational amplifier into shutdown. The shutdown terminal threshold is always referenced to the voltage on the GND terminal of the device. Therefore, when operating the device with split supply voltages (e.g.  $\pm 2.5$  V), the shutdown terminal needs to be pulled to  $V_{DD}$  (not system ground) to disable the operational amplifier.

The amplifier's output with a shutdown pulse is shown in Figure 43 and Figure 44. The amplifier is powered with a single 5-V supply and is configured as noninverting with a gain of 5. The amplifier turnon and turnoff times are measured from the 50% point of the shutdown pulse to the 50% point of the output waveform. The times for the single, dual, and quad are listed in the data tables.

Figure 37 through Figure 40 show the amplifier's forward and reverse isolation in shutdown. The operational amplifier is configured as a voltage follower ( $A_V = 1$ ). The isolation performance is plotted across frequency using 0.1  $V_{PP}$ , 2.5  $V_{PP}$ , and 5  $V_{PP}$  input signals at  $\pm 2.5$  V supplies and 0.1  $V_{PP}$ , 8  $V_{PP}$ , and 12  $V_{PP}$  input signals at  $\pm 6$  V supplies.

### circuit layout considerations

To achieve the levels of high performance of the TLC08x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- **Ground planes** – It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- **Proper power supply decoupling** – Use a 6.8- $\mu$ F tantalum capacitor in parallel with a 0.1- $\mu$ F ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- $\mu$ F ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- $\mu$ F capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- **Sockets** – Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- **Short trace runs/compact part placements** – Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- **Surface-mount passive components** – Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

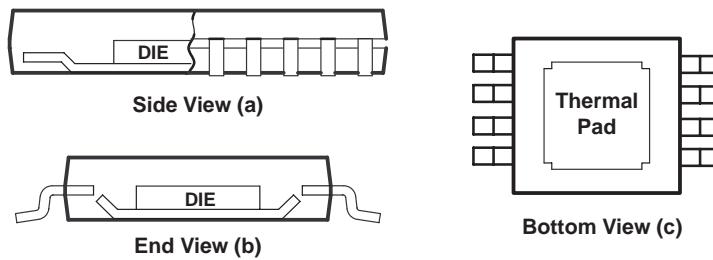
# TL080, TL081, TL082, TL083, TL084, TL085, TL08xA FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY OPERATIONAL AMPLIFIERS

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## APPLICATION INFORMATION

### general PowerPAD design considerations

The TL08x is available in a thermally-enhanced PowerPAD family of packages. These packages are constructed using a downset leadframe upon which the die is mounted [see Figure 52(a) and Figure 52(b)]. This arrangement results in the lead frame being exposed as a thermal pad on the underside of the package [see Figure 52(c)]. Because this thermal pad has direct thermal contact with the die, excellent thermal performance can be achieved by providing a good thermal path away from the thermal pad.



NOTE B: The thermal pad is electrically isolated from all terminals in the package.

**Figure 52. Views of Thermally-Enhanced DGN Package**

The PowerPAD package allows for both assembly and thermal management in one manufacturing operation. During the surface-mount solder operation (when the leads are being soldered), the thermal pad must be soldered to a copper area underneath the package. Through the use of thermal paths within this copper area, heat can be conducted away from the package into either a ground plane or other heat dissipating device. **Soldering the PowerPAD to the printed circuit board (PCB) is always required, even with applications that have low power dissipation.** This soldering provides the necessary thermal and mechanical connection between the lead frame die pad and the PCB.

Although there are many ways to properly heatsink the PowerPAD package, the following steps illustrate the recommended approach.

## APPLICATION INFORMATION

### general PowerPAD design considerations (continued)

The PowerPAD must be connected to the most negative supply voltage (GND pin potential) of the device.

1. Prepare the PCB with a top side etch pattern (see the landing patterns at the end of this data sheet). There should be etch for the leads as well as etch for the thermal pad.
2. Place five holes (dual) or nine holes (quad) in the area of the thermal pad. These holes should be 13 mils in diameter. Keep them small so that solder wicking through the holes is not a problem during reflow.
3. Additional vias may be placed anywhere along the thermal plane outside of the thermal pad area. This helps dissipate the heat generated by the TLC08x IC. These additional vias may be larger than the 13-mil diameter vias directly under the thermal pad. They can be larger because they are not in the thermal pad area to be soldered so that wicking is not a problem.
4. Connect all holes to the internal plane that is at the same potential as the ground pin of the device.
5. When connecting these holes to this internal plane, do not use the typical web or spoke via connection methodology. Web connections have a high thermal resistance connection that is useful for slowing the heat transfer during soldering operations. This makes the soldering of vias that have plane connections easier. In this application, however, low thermal resistance is desired for the most efficient heat transfer. Therefore, the holes under the TLC08x PowerPAD package should make their connection to the internal ground plane with a complete connection around the entire circumference of the plated-through hole.
6. The top-side solder mask should leave the terminals of the package and the thermal pad area with its five holes (dual) or nine holes (quad) exposed. The bottom-side solder mask should cover the five or nine holes of the thermal pad area. This prevents solder from being pulled away from the thermal pad area during the reflow process.
7. Apply solder paste to the exposed thermal pad area and all of the IC terminals.
8. With these preparatory steps in place, the TLC08x IC is simply placed in position and run through the solder reflow operation as any standard surface-mount component. This results in a part that is properly installed.

For a given  $\theta_{JA}$ , the maximum power dissipation is shown in Figure 53 and is calculated by the following formula:

$$P_D = \left( \frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

$P_D$  = Maximum power dissipation of TLC08x IC (watts)

$T_{MAX}$  = Absolute maximum junction temperature (150°C)

$T_A$  = Free-ambient air temperature (°C)

$\theta_{JA}$  =  $\theta_{JC} + \theta_{CA}$

$\theta_{JC}$  = Thermal coefficient from junction to case

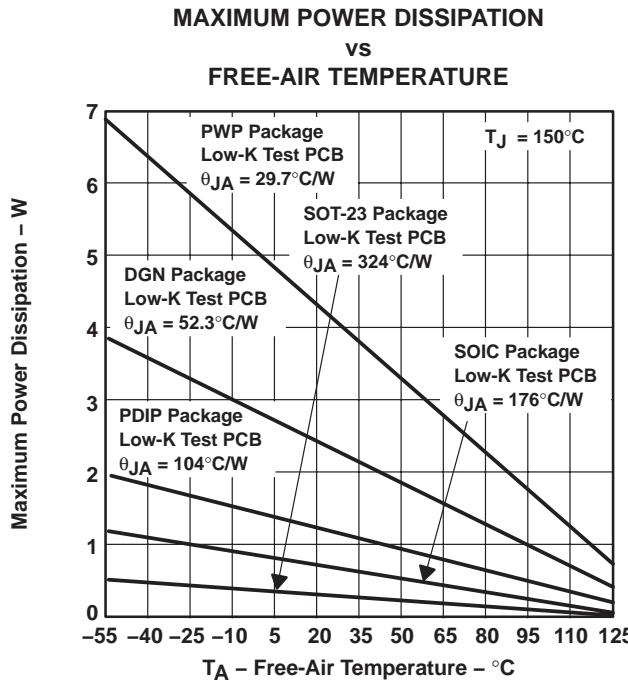
$\theta_{CA}$  = Thermal coefficient from case to ambient air (°C/W)

# TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY OPERATIONAL AMPLIFIERS

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## APPLICATION INFORMATION

### general PowerPAD design considerations (continued)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

**Figure 53. Maximum Power Dissipation vs Free-Air Temperature**

The next consideration is the package constraints. The two sources of heat within an amplifier are quiescent power and output power. The designer should never forget about the quiescent heat generated within the device, especially multi-amplifier devices. Because these devices have linear output stages (Class A-B), most of the heat dissipation is at low output voltages with high output currents.

The other key factor when dealing with power dissipation is how the devices are mounted on the PCB. The PowerPAD devices are extremely useful for heat dissipation. But, the device should always be soldered to a copper plane to fully use the heat dissipation properties of the PowerPAD. The SOIC package, on the other hand, is highly dependent on how it is mounted on the PCB. As more trace and copper area is placed around the device,  $\theta_{JA}$  decreases and the heat dissipation capability increases. The currents and voltages shown in these graphs are for the total package. For the dual or quad amplifier packages, the sum of the RMS output currents and voltages should be used to choose the proper package.

## APPLICATION INFORMATION

### macromodel information

Macromodel information provided was derived using Microsim *Parts*<sup>TM</sup>, the model generation software used with Microsim *PSpice*<sup>TM</sup>. The Boyle macromodel (see Note 1) and subcircuit in Figure 54 are generated using the TLC08x typical electrical and operating characteristics at  $T_A = 25^\circ\text{C}$ . Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

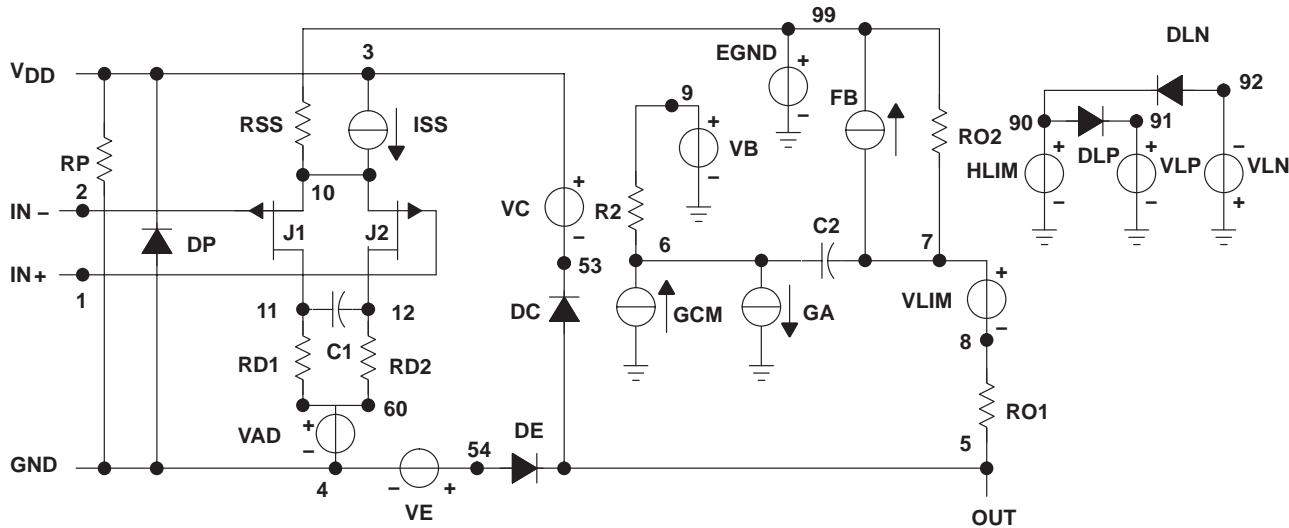
NOTE 2: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers," *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).

*PSpice* and *Parts* are trademarks of MicroSim Corporation.

# TLC080, TLC081, TLC082, TLC083, TLC084, TLC085, TLC08xA FAMILY OF WIDE-BANDWIDTH HIGH-OUTPUT-DRIVE SINGLE SUPPLY OPERATIONAL AMPLIFIERS

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## APPLICATION INFORMATION



\*DEVICE=TLC08X\_5V, OPAMP, PJF, INT

\* TLC08X\_5V – 5V operational amplifier "macromodel" sub-circuit

\* created using Parts release 8.0 on 12/16/99 at 14:03

\* Parts is a MicroSim product.

\*

\* connections:  
 \*                    non-inverting input  
 \*                    inverting input  
 \*                    positive power supply  
 \*                    negative power supply  
 \*                    output

.subckt TLC08X\_5V 1 2 3 4 5

c1 11 12 4.6015E-12

c2 6 7 8.0000E-12

css 10 99 986.29E-15

dc 5 53 dy

de 54 5 dy

dip 90 91 dx

dln 92 90 dx

dp 4 3 dx

egnd 99 0 poly(2) (3,0) (4,0) 0 .5 .5

fb 7 99 poly(5) vb vc ve vlp vln 0 13.984E6 -1E3 1E3

14E6 -14E6

ga	6	0	11	12	402.12E-6
gcm	0	6	10	99	1.5735E-6
ioff	0	6	dc	1.212E-6	
iss	3	10	dc	130.40E-6	
hlim	90	0	vlim	1K	
j1	11	2	10	jx1	
j2	12	1	10	jx2	
r2	6	9		100.00E3	
rd1	4	11		2.4868E3	
rd2	4	12		2.4868E3	
ro1	8	5	10		
ro2	7	99	10		
rp	3	4		2.8249E3	
rss	10	99		1.5337E6	
vb	9	0	dc	0	
vc	3	53	dc	1.5537	
ve	54	4	dc	.84373	
vlim	7	8	dc	0	
vlp	91	0	dc	117.60	
vln	0	92	dc	117.60	
.model	dx	D(Is=800.00E-18)			
.model	dy	D(Is=800.00E-18 Rs=1m Cjo=10p)			
.model	jx1	PJF(Is=80.000E-15 Beta=1.2401E-3 Vto=-1)			
.model	jx2	PJF(Is=80.000E-15 Beta=1.2401E-3 Vto=-1)			
.ends					

Figure 54. Boyle Macromodel and Subcircuit

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC080AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC080AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC080CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080CDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080CDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080IDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080IDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC080IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC080IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC081CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDGMR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IDGMR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC081IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC081IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC082AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC082AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC082CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC082CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC082ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC082IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC082IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083AID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083AIN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083AINE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
no Sb/Br)								
TLC083CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083CDGQR	ACTIVE	MSOP-Power PAD	DGQ	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083CDGQRG4	ACTIVE	MSOP-Power PAD	DGQ	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083IDGQ	ACTIVE	MSOP-Power PAD	DGQ	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083IDGQG4	ACTIVE	MSOP-Power PAD	DGQ	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC083IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC083INE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC084AID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084AIDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084AIDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084AIDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084AIN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC084AINE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC084AIPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084AIPWPR	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084AIPWPRG4	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
no Sb/Br)								
TLC084CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
TLC084CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC084CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC084CPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084CPWPG4	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084CPWPR	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084CPWPRG4	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC084IPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084IPWPG4	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084IPWPR	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC084IPWPRG4	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC085AID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085AIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085AIDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085AIN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC085AINE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC085AIPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC085CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085CDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085CDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085CN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC085CNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC085CPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC085IDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085IDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC085IPWP	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TLC085IPWPG4	ACTIVE	HTSSOP	PWP	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

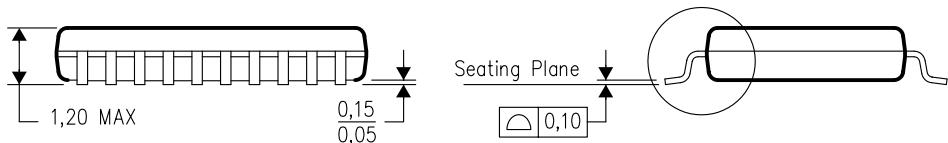
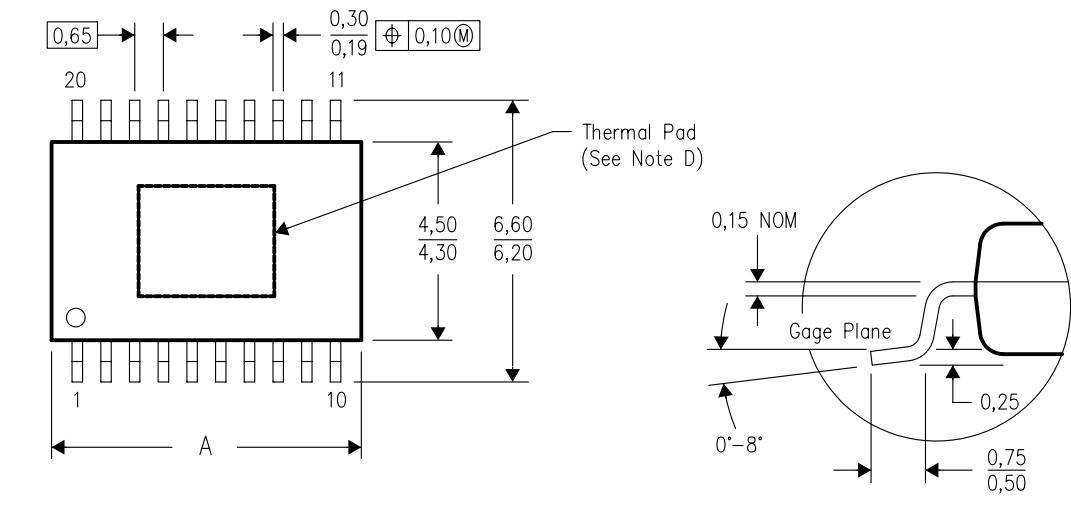
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PWP (R-PDSO-G\*\*)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20 PIN SHOWN



PINS **		14	16	20	24	28
DIM						
A	MAX	5,10	5,10	6,60	7,90	9,80
A	MIN	4,90	4,90	6,40	7,70	9,60

4073225/H 12/05

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- E. Falls within JEDEC MO-153

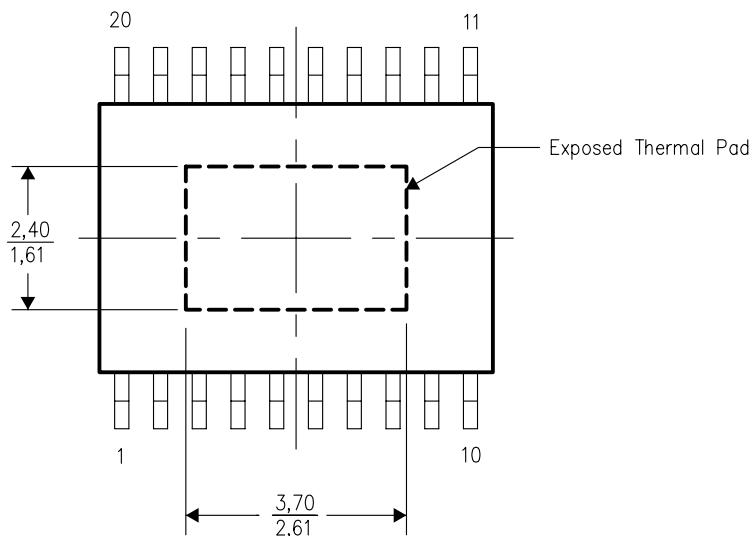
PowerPAD is a trademark of Texas Instruments.

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. When the thermal pad is soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground plane or special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

NOTE: All linear dimensions are in millimeters

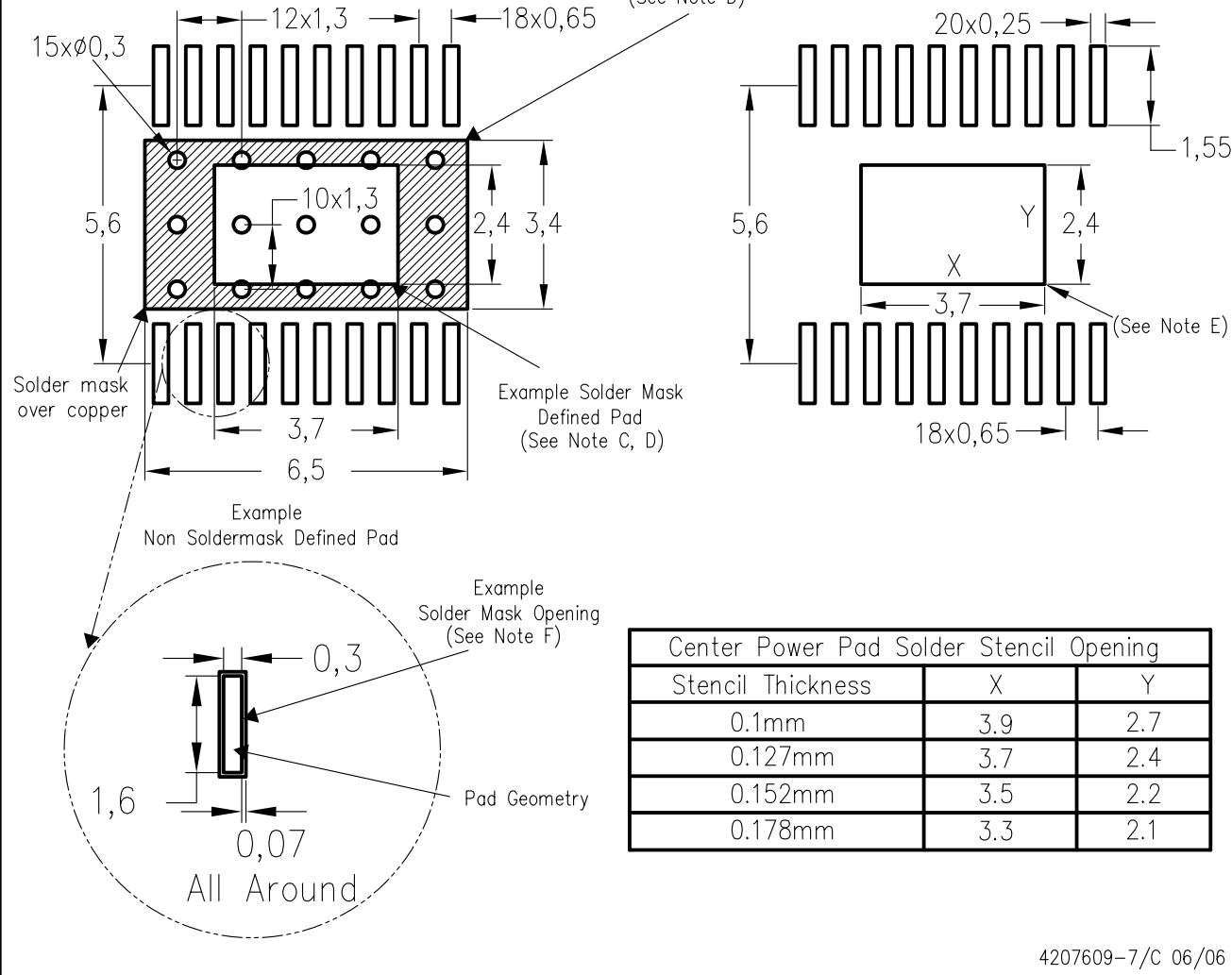
Exposed Thermal Pad Dimensions

PWP (R-PDSO-G20) PowerPAD™

Example Board Layout  
Via pattern and copper pad size  
may vary depending on layout constraints

Increasing copper area will enhance thermal performance  
(See Note D)

Stencil Openings  
Based on a stencil thickness  
of .127mm (.005inch).  
Reference table below for other  
solder stencil thicknesses



4207609-7/C 06/06

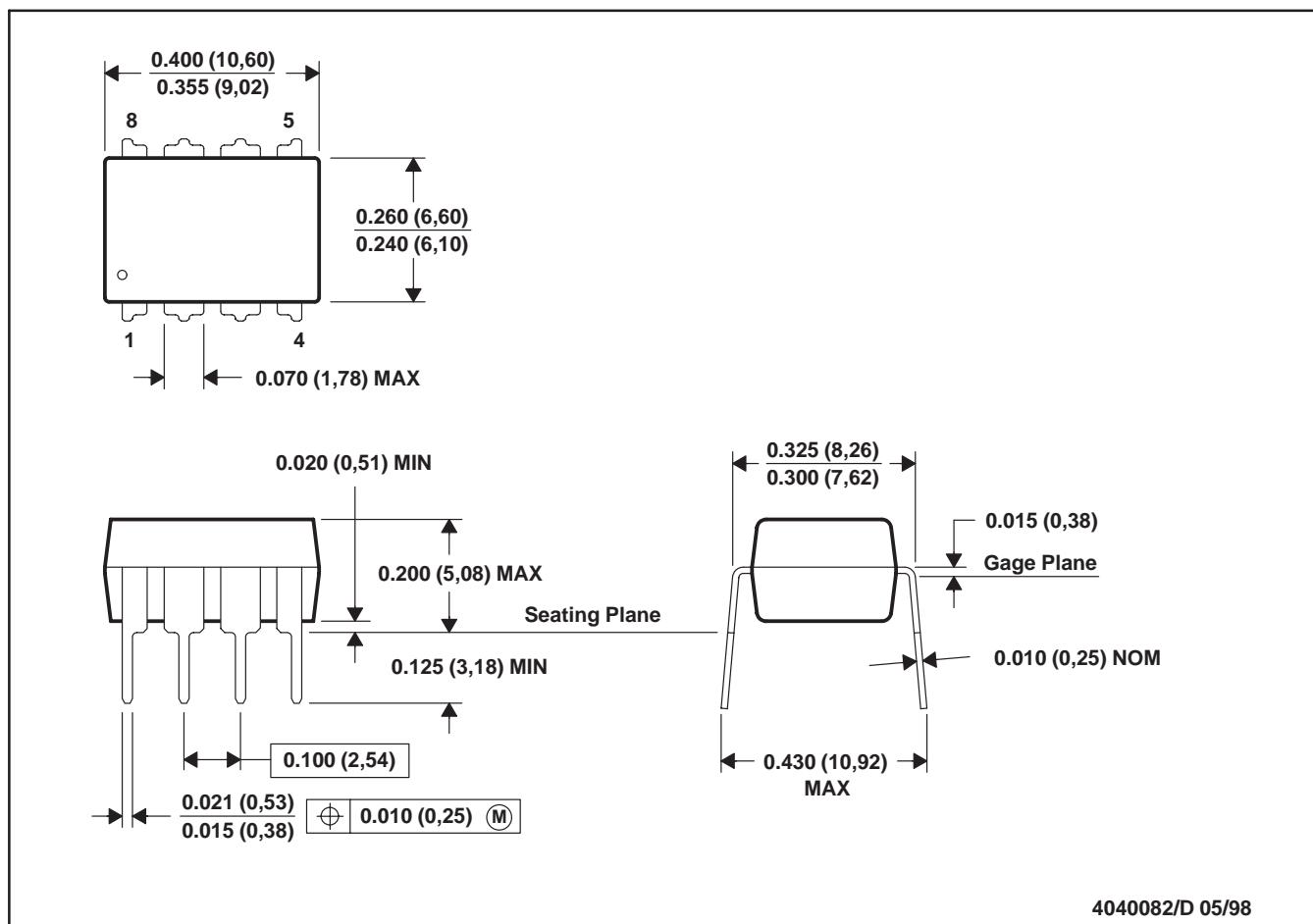
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PowerPAD is a trademark of Texas Instruments.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



4040082/D 05/98

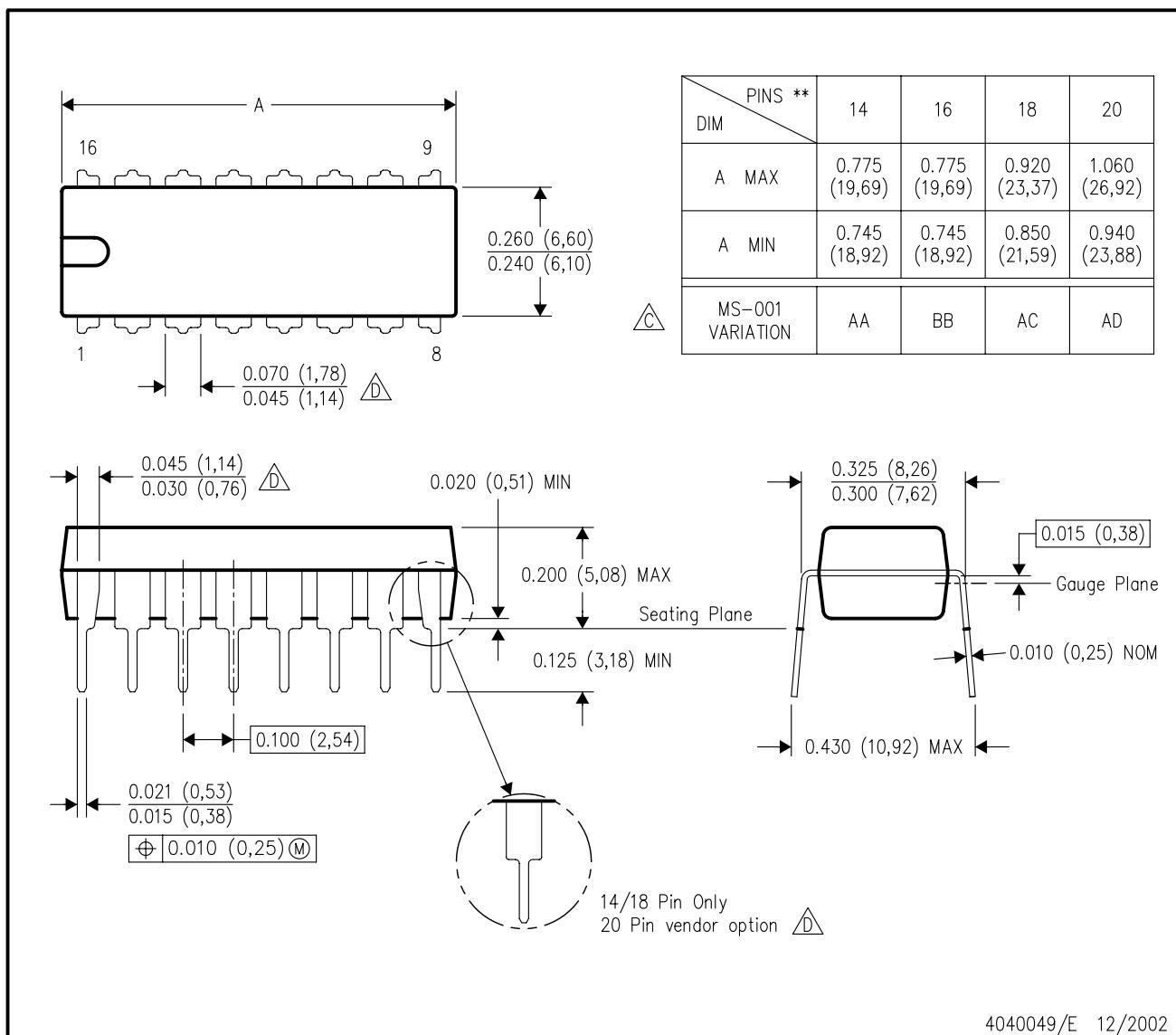
NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001

For the latest package information, go to [http://www.ti.com/sc/docs/package/pkg\\_info.htm](http://www.ti.com/sc/docs/package/pkg_info.htm)

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



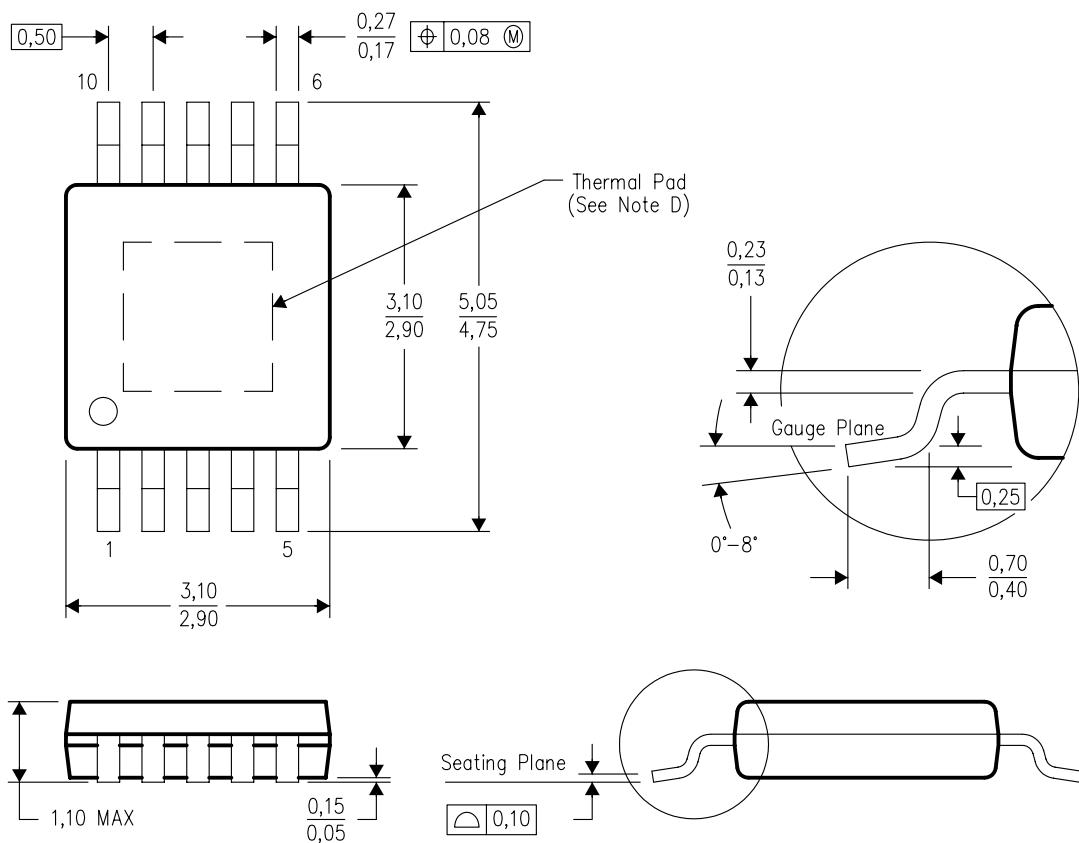
NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

## DGQ (S-PDSO-G10)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



4073273/D 02/04

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- E. Falls within JEDEC MO-187 variation BA-T.

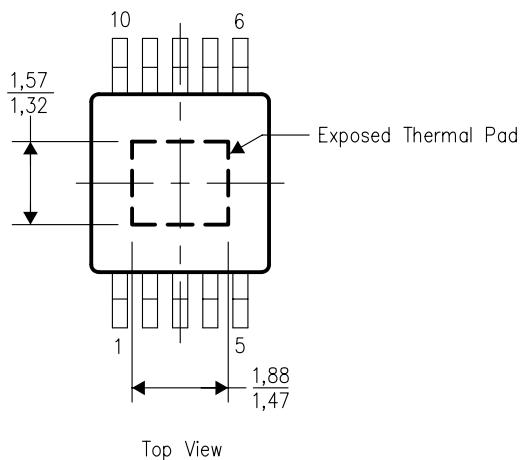
PowerPAD is a trademark of Texas Instruments.

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. When the thermal pad is soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground or power plane (whichever is applicable), or alternatively, a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



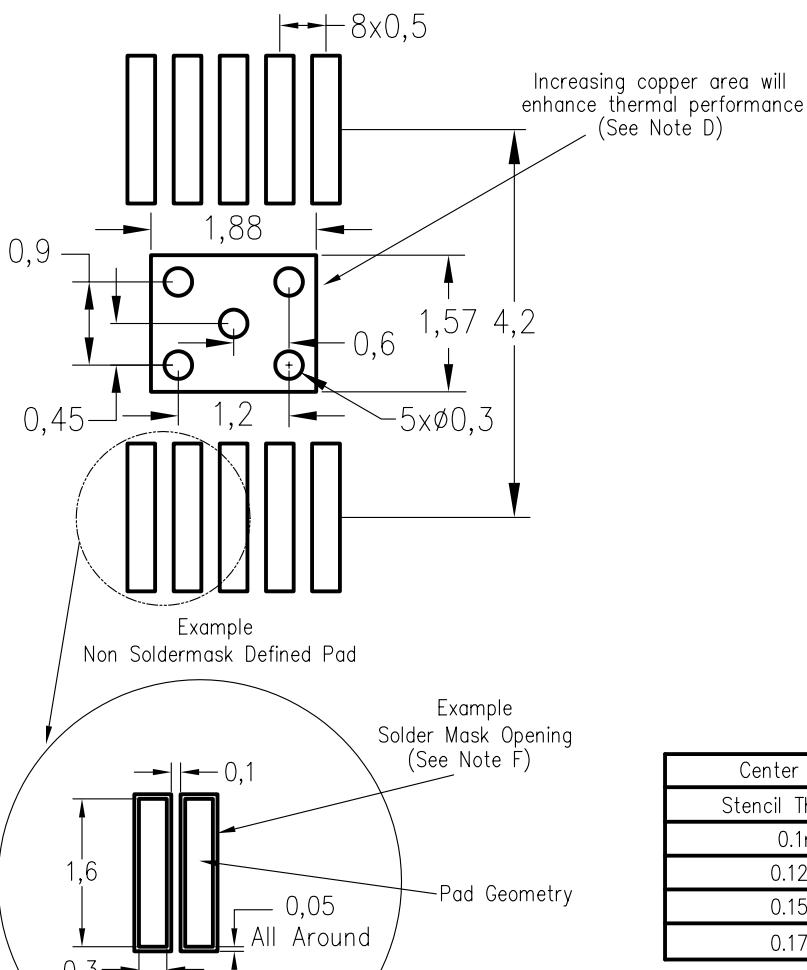
Top View

NOTE: All linear dimensions are in millimeters

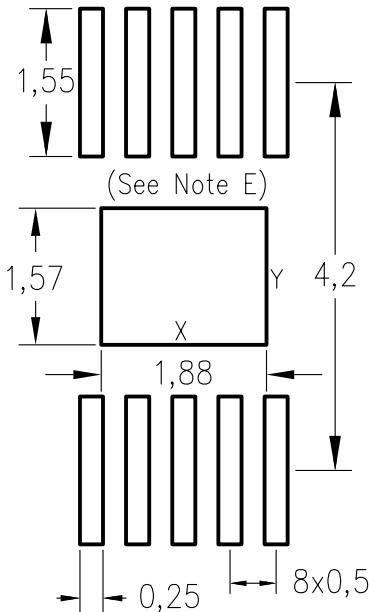
Exposed Thermal Pad Dimensions

## DGQ (R-PDSO-G10) PowerPAD™

Example Board Layout  
Via pattern and copper pad size  
may vary depending on layout constraints



Stencil Openings  
Based on a stencil thickness  
of .127mm (.005inch).  
Reference table below for other  
solder stencil thicknesses



Center Power Pad Solder Stencil Opening	X	Y
Stencil Thickness		
0.1mm	2.0	1.7
0.127mm	1.88	1.57
0.152mm	1.75	1.45
0.178mm	1.65	1.35

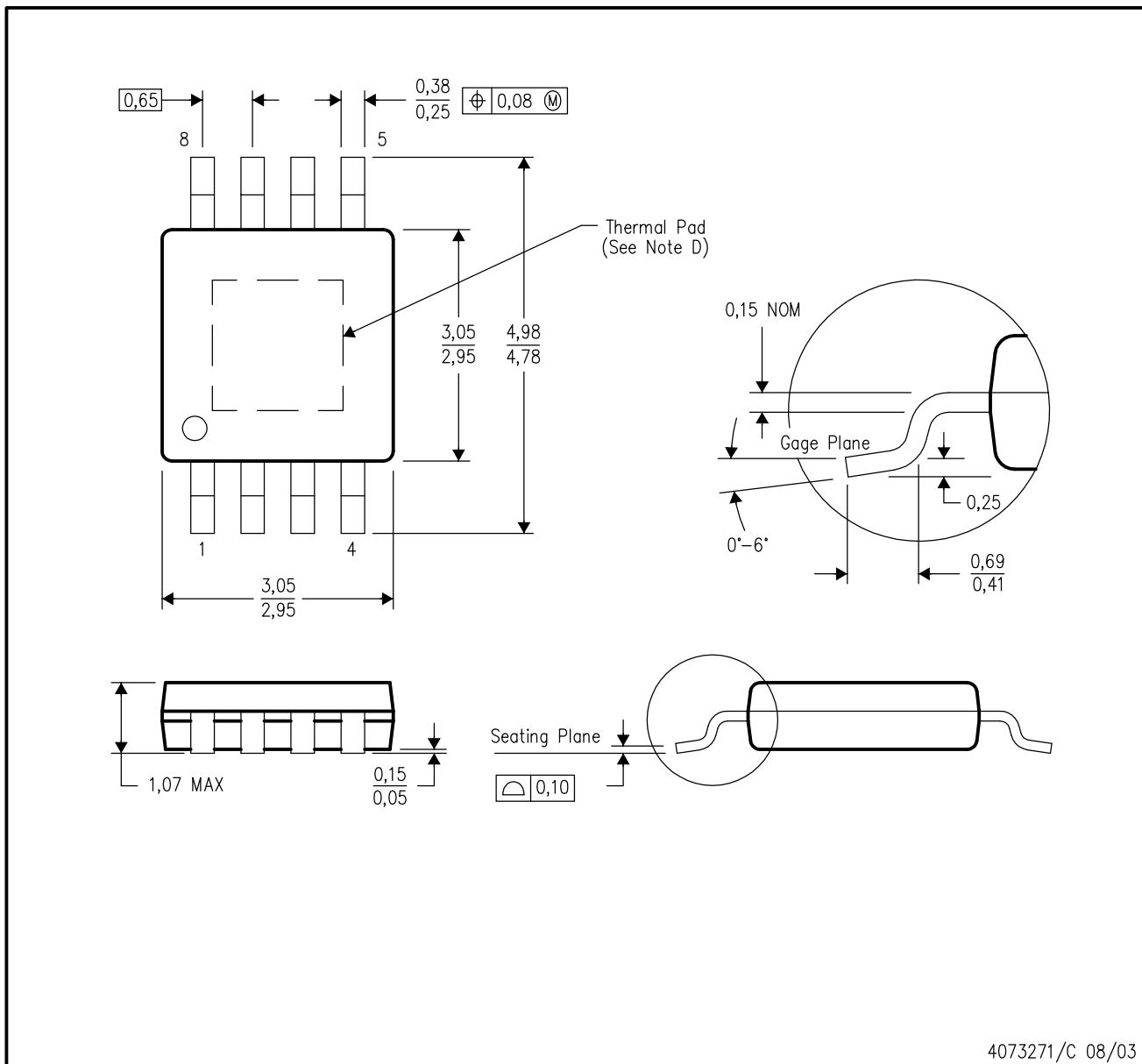
4207733/A 02/06

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



4073271/C 08/03

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- Falls within JEDEC MO-187

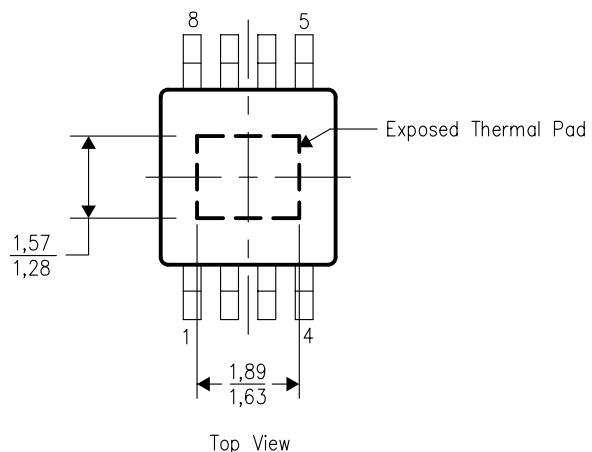
PowerPAD is a trademark of Texas Instruments.

## THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. When the thermal pad is soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground or power plane (whichever is applicable), or alternatively, a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

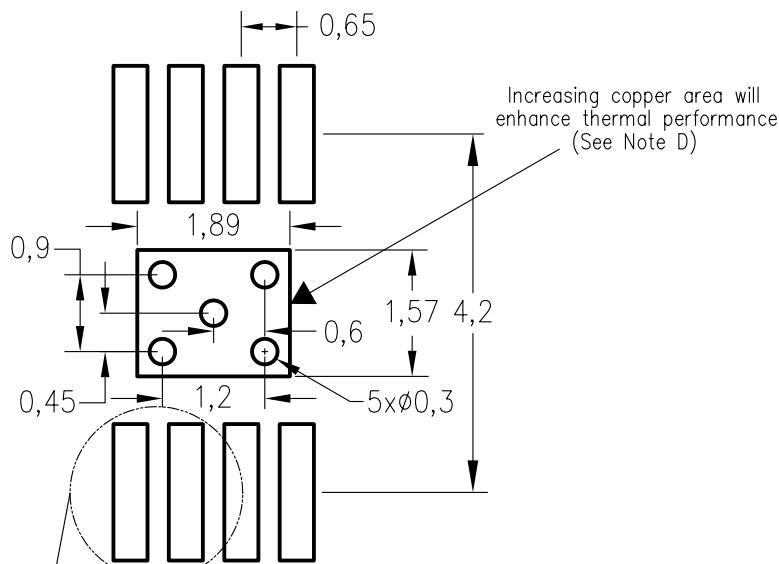


NOTE: All linear dimensions are in millimeters

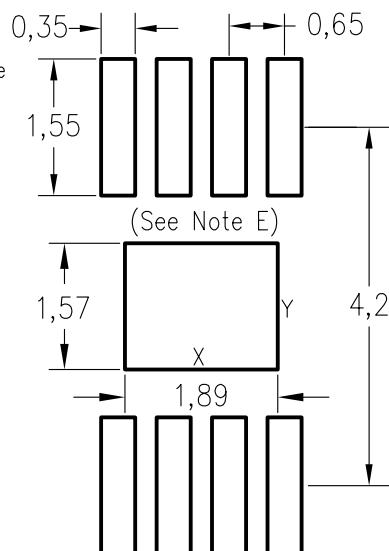
Exposed Thermal Pad Dimensions

DGN (R-PDSO-G8) PowerPAD™

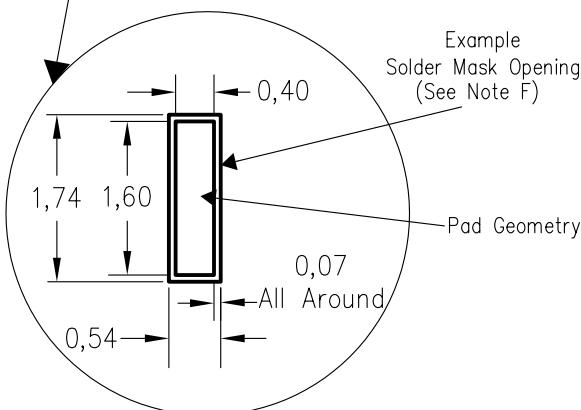
Example Board Layout  
Via pattern and copper pad size  
may vary depending on layout constraints



Stencil Openings  
Based on a stencil thickness  
of .127mm (.005inch).  
Reference table below for other  
solder stencil thicknesses



## Example Non Soldermask Defined Pad



Example  
Solder Mask Opening  
(See Note F)

### Center Power Pad Solder Stencil Opening

Stencil Thickness	X	Y
0.1mm	2.0	1.7
0.127mm	1.89	1.57
0.152mm	1.75	1.45
0.178mm	1.65	1.35

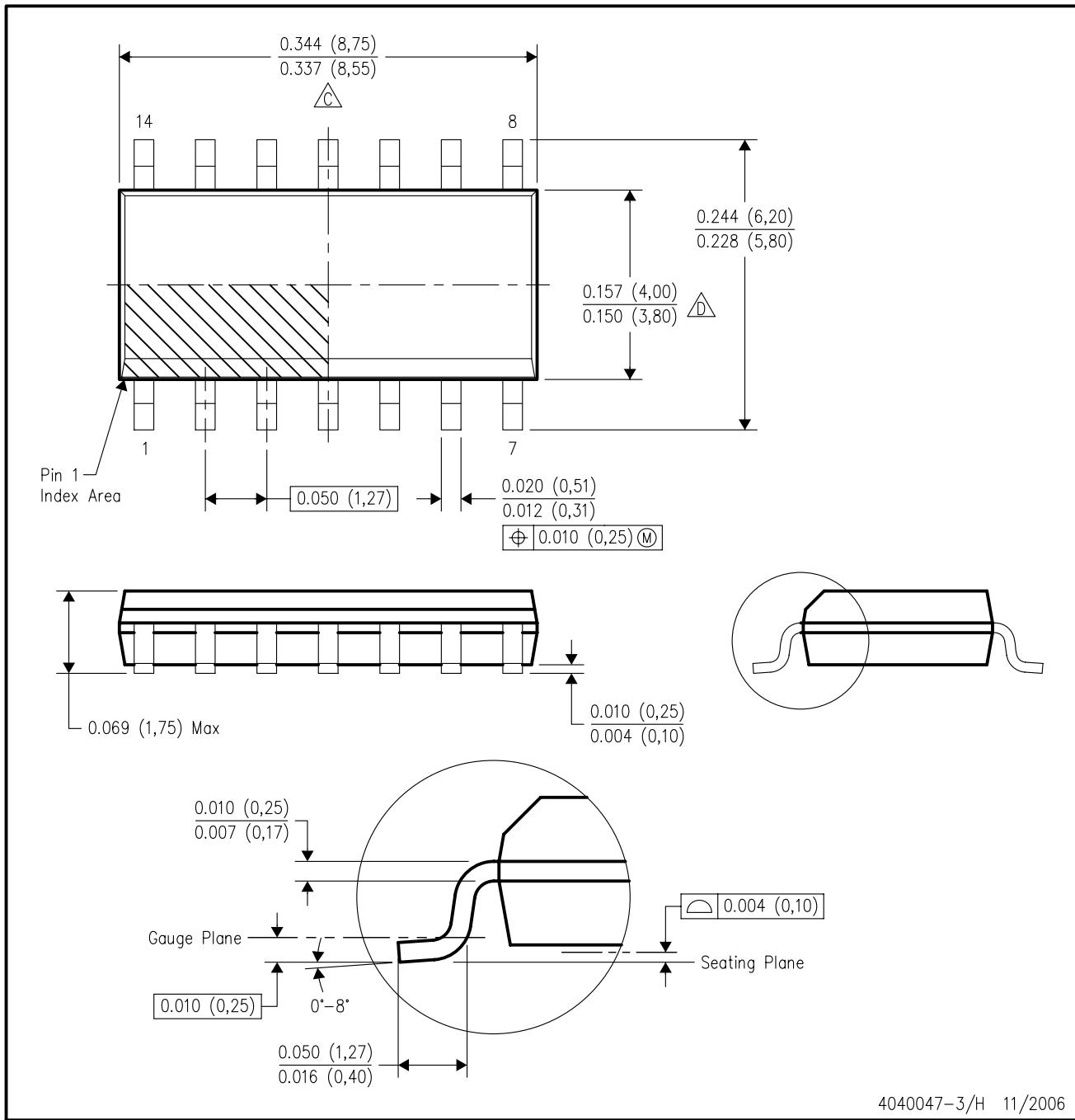
4207737/A 02/06

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

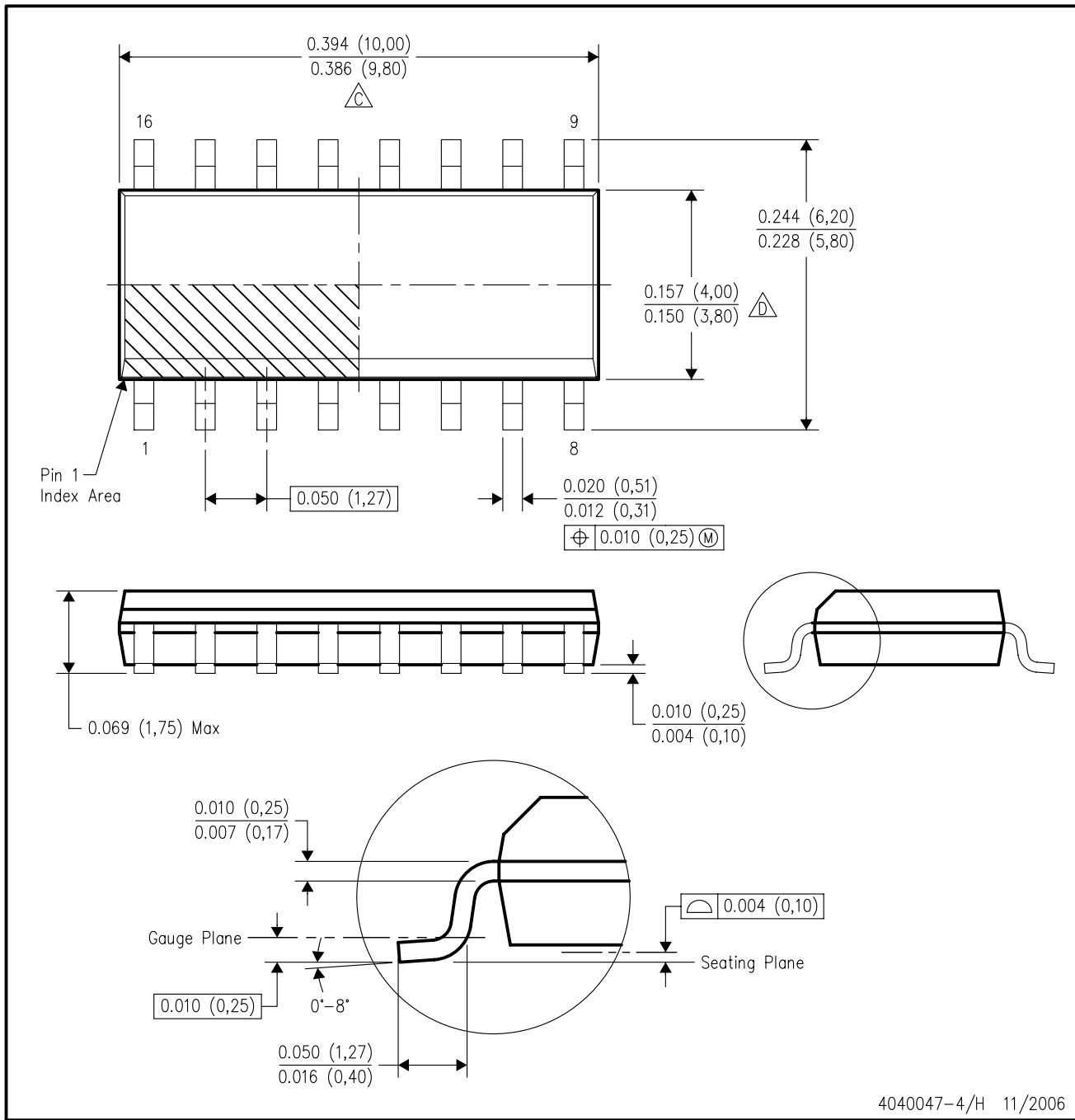
## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

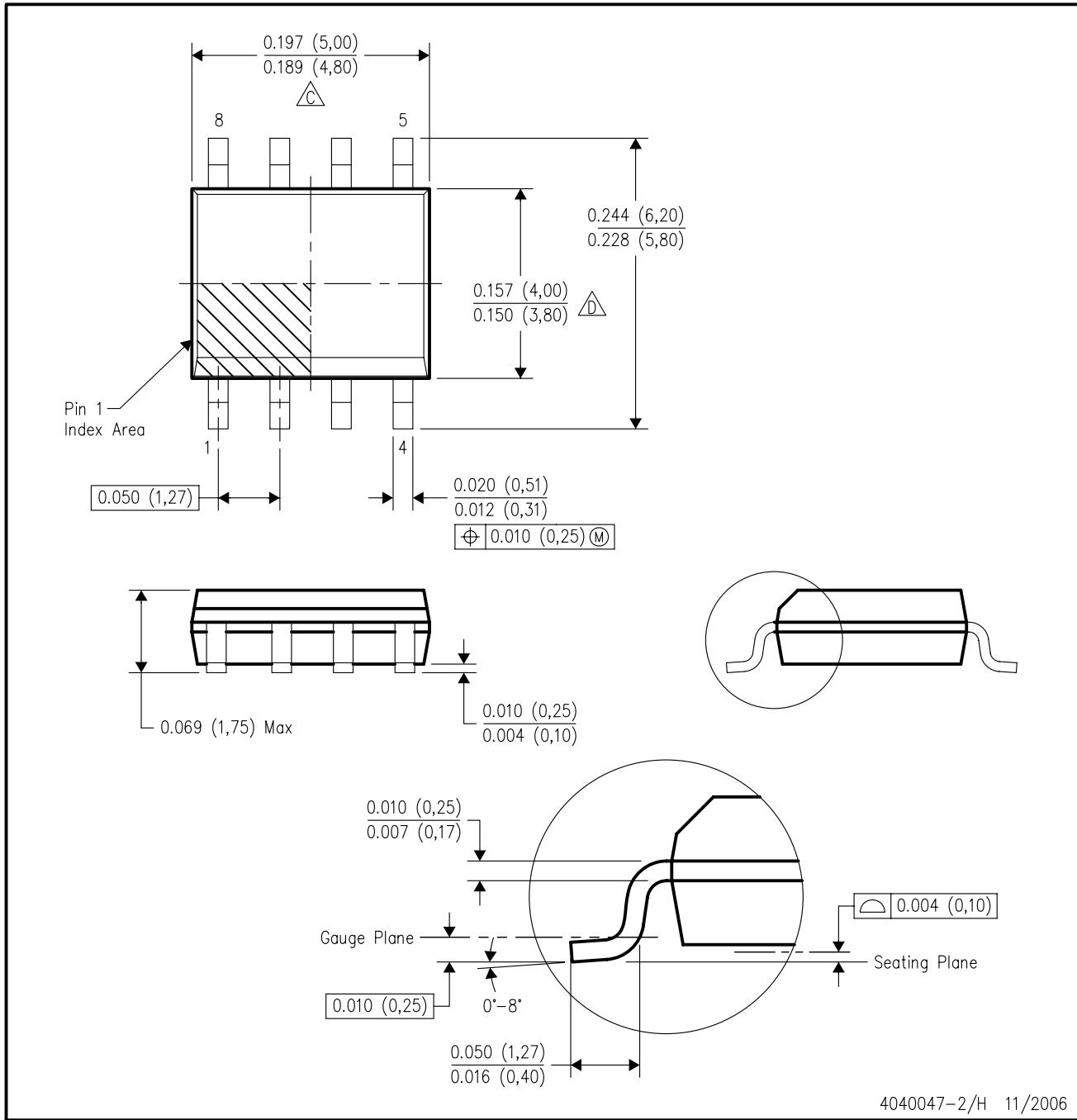
C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.

## D (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.

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		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

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